

MOS INTEGRATED CIRCUIT $\mu PD9930$

LINEAR CODEC FOR DIGITAL CELLULAR TELEPHONE

The μ PD9930 is a +3 V single power operation, low power consumption linear CODEC LSI developed for digital cellular telephone use.

CODEC has a wide dynamic use.

This IC also features a microphone/receiver amplifier, a tone generator, DAI (Digital Audio Interface: conforming to GSM11.10), and a power-saving function. These functions can be controlled by microcontroller.

In addition, 21 mW (TYP.) low power consumption is enabled during 3 V operation.

FEATURES

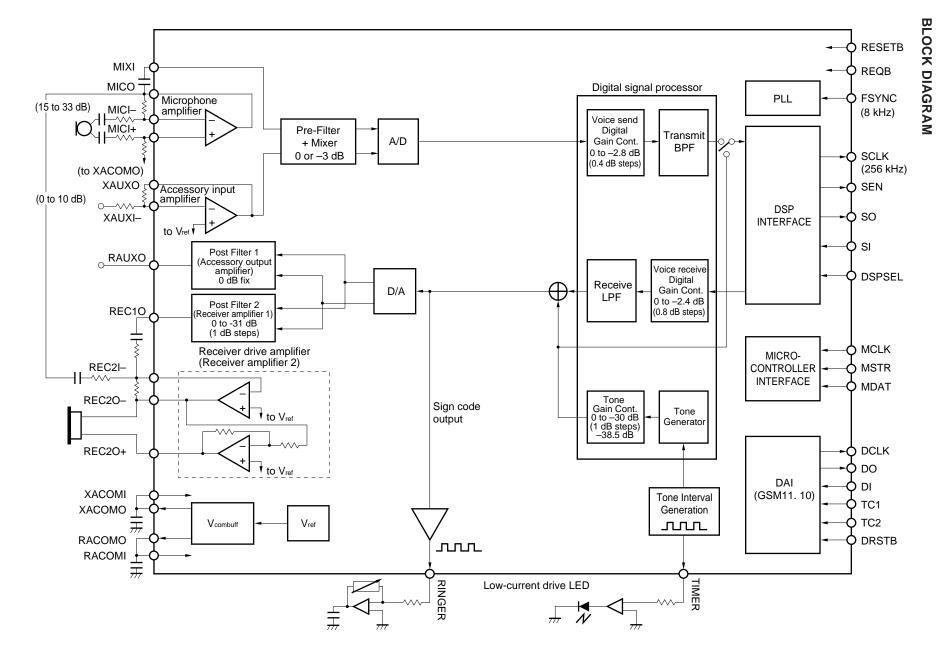
- +3 V single power supply
- Low power consumption In operation: 7 mA (TYP.) (V_{DD} = 3 V) In stand-by mode: 50 μ A (TYP.) (V_{DD} = 3 V)
- CODEC
 - 13-bit precision linear coding
 - Transmission level can be controlled by microcontroller.
- · Analog input/output funciton
 - · Low noise microphone amplifier
 - High output receiver amplifier
 Piezo-electric receiver can be directly driven.
 Gain canbe controlled by microcontroller.
 - On-chip amplifier for accessory input/output
- Tone generator
 - Frequency, generating pattern and gain can be controlled by microcontroller.
 - DTMF generation function
 - Various service tone generation function
 - GSM triple tone generation function
 - Desired tone frequency can be registered (0.3 to 3.4 kHz)

- DAI
 - Conforming to GSM11.10
 - Test mode can be set by terminal or microcontroller command.
- · Stand-by mode
 - Rise time at time of stand-by clearing: 30.5 ms (TYP.)
- Master clock generation PLL (external clock input: 8 kHz)
- Tone interrupt pattern output function
- · Ringer output function

ORDERING INFORMATION

Part NumberPackageμPD9930G-2244-pin plastic QFP (10 × 10 mm)

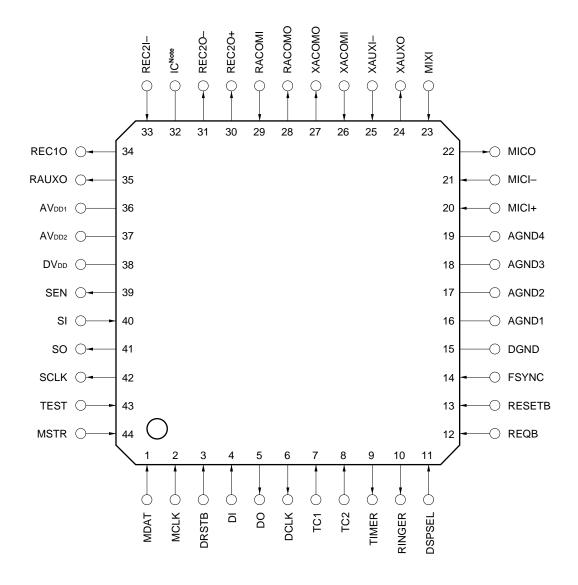
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PIN CONFIGURATION (Top View)

44-pin plastic QFP (10 x 10 mm)



Note Internal connection; leave unconnected



Pin Name

AGND1-AGND4 : Analog Ground

AVDD1, AVDD2 : Analog Power Supply

DCLK : DAI (Digital Audio Interface) Clock Output

DGND : Digital Ground
DI : DAI Serial Input
DO : DAI Serial Output

DRSTB : DAI Reset

DSPSEL : Digital Signal Processor Select

DV_{DD} : Digital Power Supply

FSYNC : Frame Synchronization Signal Input

IC : Internally Connected

MCLK : Microcontroller Synchronous Clock

MDAT : Microcontroller Serial Data

MICI+ : Microphone Amplifier Input Non-Inverted
MICI- : Microphone Amplifier Input Inverted

MICO : Microphone Amplifier Output

MIXI : Mixer Input

MSTR : Microcontroller Strobe

RACOMI : Receive Common Reference Voltage Input RACOMO : Receive Common Reference Voltage Output

RAUXO : Receive Auxiliary Amplifier Output

REC1O : Receive Amplifier 1 Output

REC2I- : Receive Amplifier 2 Input Inverted

REC2O+ : Receive Amplifier 2 Output Non-Inverted REC2O- : Receive Amplifier 2 Output Inverted

REQB : Request RESETB : Reset RINGER : Ringer

SCLK : Serial Data Synchronous Clock Output

SEN : Serial Data Output Enable

SI : Serial Data Input SO : Serial Data Output TC1, TC2 : DAI Mode Control

TEST : Test TIMER : Timer

XACOMI : Transmit Common Reference Voltage Input
XACOMO : Transmit Common Reference Voltage Output
XAUXI- : Transmit Auxiliary Amplifier Input Inverted

XAUXO : Transmit Auxiliary Amplifier Output



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1. PIN FUNCTIONS

1.1 LIST OF PIN FUNCTIONS

Table 1-1 List of Pin Functions (1/2)

Pin No.	Pin Name	Input/Output		Functi	ion			
1	MDAT	Input	Microcontroller interface serial input					
2	MCLK	Input	Microcontroller interface clock input					
3	DRSTB	Input	DAI (Digital Audio Interface) reset inp	out				
			This is reset at low level. Internally p	oulled h	igh.			
4	DI	Input	DAI serial input Internally pulled high.					
5	DO	Output	DAI serial output					
			Hi-Z in normal operation (TC1 = TC2	= low l	level)			
6	DCLK	Output	DAI clock output (104 kHz) Hi-Z in normal operation					
7	TC1	Input	DAI mode control	TC2	TC1	Test mode specification		
			Selection of test mode specified by GSM11.10 in combination with TC1	L	L	Normal operation		
			and TC2	L	Н	Speech encoder test mode		
8	TC2	Input	L: Low level	Н	L	Speech decoder test mode		
			H: High level	Н	Н	Acoustic device test mode		
			TC1 and TC2 pins are internally pulled down.					
9	TIMER	Output	Timer output. Output of rectangular wave synchronized with tone intermittent pattern.					
10	RINGER	Output	Ringer tone output. Output of rectan quency.	gular w	ave syı	nchronized with tone fre-		
11	DSPSEL	Input	Selection of DSP interface input/outp Connect to V _{DD} or GND. (V _{DD} = mod		•			
12	REQB	Input	Input of DSP interface data transmit in Serial data can be input/output at low		signal.			
13	RESETB	Input	System reset input. This is reset at I Reset when turning power on.	ow leve	el. Initia	alizes all control registers.		
14	FSYNC	Input	Send/receive frame synchronization s	signal (8 kHz)	input		
15	DGND	_	Digital ground. Connect to a digital g	ground	line nea	ar μPD9930 pins.		
16	AGND1	_	Analog ground. Connect to an analo	g grour	nd line i	near μPD9930 pins.		
17	AGND2	_						
18	AGND3	_						
19	AGND4	_						
20	MICI+	Input	Microphone amplifier non-inverted inp	out				
21	MICI-	Input	Microphone amplifier inverted input					
22	MICO	Output	Microphone amplifier output. Connect microphone amplifier gain adjust resistor. Outputs sidetone signal to REC2I- pin.					
23	MIXI	Input	Pre-filter + mixer input					
24	XAUXO	Output	Accessory input amplifier output. Connect accessory input amplifier gain adjust resistor.					

*



Table 1-1 List of Pin Functions (2/2)

Pin No.	Pin Name	Input/Output	Function
25	XAUXI-	Input	Accessory input amplifier inverted input
26	XACOMI	Input	Voice send internal reference voltage input
27	XACOMO	Output	Voice send internal reference voltage (1.2 V) output
28	RACOMO	Output	Voice receive internal reference voltage (1.2 V) output
29	RACOMI	Input	Voice receive internal reference voltage input
30	REC2O+	Output	Receiver amplifier 2 non-inverted output
31	REC2O-	Output	Receiver amplifier 2 inverted output
32	IC	_	Internal connection; leave unconnected
33	REC2I-	Input	Receiver amplifier 2 inverted input
			Connect sidetone gain adjust resistor.
34	REC10	Output	Receiver amplifier 1 output
35	RAUXO	Output	Accessory output amplifier output
36	AV _{DD1}	_	Analog power. Connect to an analog power supply line near μPD9930 pins.
37	AV _{DD2}	_	
38	DV _{DD}	_	Digital power. Connect to a digital power supply line near μ PD9930 pins.
39	SEN	Output	DSP interface enable signal output
40	SI	Input	DSP interface serial input
41	SO	Output	DSP interface serial output
42	SCLK	Output	DSP interface clock output (256 kHz)
43	TEST	Input	Set at high level
44	MSTR	Input	Microcontroller interface strobe signal input

* Caution Short-circuit the XACOMI and XACOMO pins at a location as close to the pins of the μPD9930 as possible. Connect a capacitor (chip capacitor or electrolytic capacitor) between this short-circuited portion and analog ground.

The same applies to the RACOMI and RACOMO pins.

The transmission/reception level is determined by these reference pins. Therefore, make sure that these pins are not affected by noise or fluctuation of ground potential due to current.

 \star



1.2 PIN EQUIVALENT CIRCUIT Type 1 Type 2 AV_{DD} AV_{DD} Analog input Analog input \bigcirc To internal circuit \bigcirc To internal circuit AGND AGND Pin Name MICI+, MICI-, XAUXI-, REC2I-Pin Name MIXI, XACOMI, RACOMI AV_{DD} Type 3 - DV_{DD} Type 4 Analog output CMOS input \bigcirc From internal circuit (0)To internal circuit AGND DGND Pin Name MDAT, MCLK, DSPSEL, REQB, RESETB, FSYNC, TEST, MSTR Pin Name MICO, XAUXO, XACOMO, RACOMO, REC2O+, REC2O-, REC1O, RAUXO Type 5 DV_DD Type 6 Note DV_DD Mask input **CMOS** input **CMOS** input To internal \bigcirc circuit To internal circuit **DGND DGND** Pin Name SI Pin Name TC1, TC2 Type 7 Note Type 8 DV_DD DV_DD $\mathsf{DV}_{\mathsf{DD}}$ Ρ CMOS output CMOS input From internal \bigcirc To internal circuit circuit → DGND **DGND** Pin Name DRSTB. DI Pin Name TIMER, RINGER, SEN, SO, SCLK Type 9 ○ Enable signal DV_{DD} CMOS output \bigcirc From internal circuit **DGND** Pin Name DO, DCLK

Note In normal mode, set the output of drive IC side to high impedance for reducing power consumption.



★ 2. BLOCK FUNCTIONS

2.1 CODEC

2.1.1 Audio Codec

Audio analog signal and linear code conversion.

- Input/output format: 16 bits (2's complement)
- · Accuracy: 13 bits

2.1.2 Audio Analog Input

Includes microphone input and accessory input.

(1) Microphone amplifier

Amplifiers differential input signals from the microphone to the required gain.

(Including gain setting resistance)

20 pF

 $0.6\ V_{0-p}$

(2) Accessory input amplifier

Amplifiers the accessory input signal to the required gain.

(3) Pre-filter + mixer

Maximum capacitive load

Maximum output level

Selects the output signal of microphone amplifier and accessory input amplifier, and inputs these to A/D converter after controlled gain.

Amplifier Function	Microphone Amplifier	Accessory Input Amplifier	Pre-filter + Mixe
Gain setting method	External resistor	External resistor	Microcontroller command
Gain setting range	15 to 33 dB 20 log R2/R1 (dB)	0 to 10 dB 20 log R3 (dB)	0 or -3 dB
Minimum resistive load	50 kΩ	300 kΩ	_

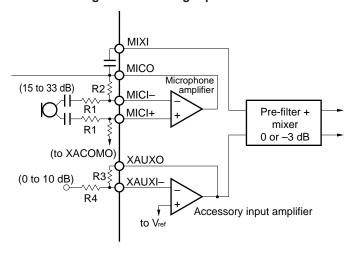
Table 2-1 Analog Input Function

Figure 2-1 Analog Input Block

20 pF

 $0.6\ V_{0-p}$

(Including gain setting resistance)





2.1.3 Audio Analog Output

Includes receiver output and accessory output. Sidetone addition is also possible.

(1) Post filter 2 (receiver amplifier 1)

This circuit adjusts the gain of D/A differential output signal (volume control), and then converts it to single output signal.

(2) Receiver drive amplifier (receiver amplifier 2)

This is differential output amplifier that can directly drive a piezo-electric receiver (when using a dynamic receiver, an additional external amplifier is necessary). The sidetone is added in this circuit.

(3) Post filter 1 (accessory output amplifier)

This circuit converts D/A differential output signal to single output signal. Connected to the earphone of the head set (capacitance load), etc.

Amplifier	Receiver Amplifier 1	Receiver Amplifier 2	Accessory Output Amplifier		
Gain setting method	Microcontroller command	External resistor	_		
Gain setting range	0 to -31 dB (1 dB steps)	Voice receive signal gain: $-\infty \text{ to } + 10 \text{ dB}$ $20 \log \frac{R3}{R2} \text{ (dB) } + 6 \text{ dB}^{\text{Note}}$ Sidetone signal gain: $-\infty \text{ to } + 3 \text{ dB}$ $20 \log \frac{R3}{R1} \text{ (dB) } + 6 \text{ dB}^{\text{Note}}$			
Minimum resistive load	100 kΩ	2 kΩ	100 kΩ		
Maximum capacitive load	20 pF	60 nF	100 pF		
Maximum output level	0.6 V _{0-p}	4 V _{p-p} (Differential output)	0.6 V _{0-p}		

Table 2-2 Analog Output Functions

Note Conversion result (single output → differential output)

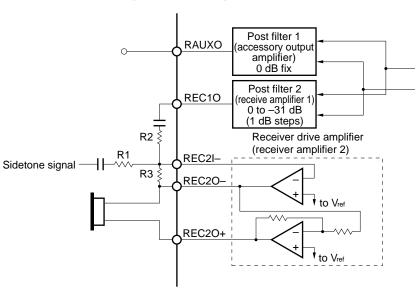


Figure 2-2 Analog Output Block

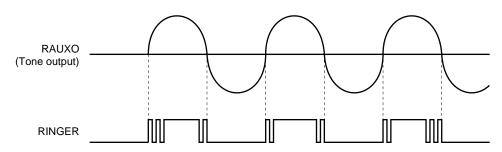


2.1.4 Audio Digital Accessory Output

(1) Ringer output (RINGER pin)

- Outputs rectangular waves of the same signal frequency as tone signal frequency.
- The output is controlled by turning off power to the output buffer with a control register.

Figure 2-3 RINGER Output



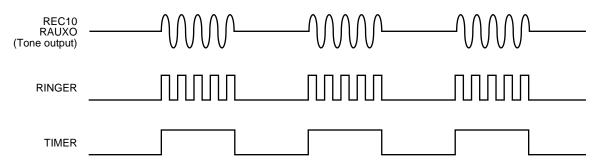
The RINGER signal tends to bounce when the tone output (RAUXO) signal crosses its zero level, and this tendency increases as the tone output gain decreases (lower than 0 dB).

When using RINGER pin, tune the tone output gain by TNGCR (Tone gain control register) to 0 dB.

(2) Timer (tone interval) output (TIMER pin)

Outputs rectangular waves of the same pattern as the tone signal interrupt pattern. This is used to make the LED blink in synchronization with the ringer tone.

Figure 2-4 Digital Accessory Output Waveform



2.1.5 Audio Digital Signal Processor

Send signal digital BPF processing, receive signal digital LPF processing, transmission level (digital gain) control, and tone generation processing.

(1) Voice send signal digital gain fine adjustment function

Performs gain fine adjustment for voice send signal by digital coefficient multiplication. Together with prefilter gain adjustment, fine adjustment is possible at a width of 5.8 dB.

(2) Voice receive signal digital gain fine adjustment function

Performs fine adjustment of gain for voice receive signal by digital coefficient multiplication.

(3) Tone generation function

Generates single-tone and dual-tone audible signals. Tone frequency, interrupt pattern, gain, generation/stop can be controlled by microcontroller command. GSM triple tone can be generated by special command.



Table 2-3 Digital Gain Control Functions

	Voice Send Signal Gain Control	Voice Receive Signal Gain Control	Tone Gain Control
Gain setting method	Microcontroller command	Microcontroller command	Microcontroller command
Gain setting range	0 to -2.8 dB (0.4 dB steps)	0 to -2.4 dB (0.8 dB steps)	0 to -30 dB (1 dB steps), -38.5 dB

2.1.6 Power Up/Down Control

The μ PD9930 includes a power down function for reducing power consumption. Power down control is by the two methods described below.

(1) Input/output amplifier power up/down control

Power up/down for both the input and output amplifiers can be controlled.

When the power down function is used for all input amplifiers, both pre-filter and A/D enter the power down state. When the power down function is used for the accessory output amplifier and the receiver 1 amplifier, the D/A also enters power down state.

(2) Stand-by mode

Low power consumption can be realized in the mode in which all chip operation is stopped. The stand-by mode is set by power down command. Operation restarts by power up command.

The following control registers are used to enable the control described above.

Control Method	Registers Used
Power up/down control of input/output amplifier (not including receiver amplifier 2)	Input/output amplifier control register (AMPCR)
Power up/down control of receiver amplifier 2	Send analog gain/receiver amplifier 2 control register (TXGCR)
Set/clear of standby mode	Power up control command (PUPCMD)
	Power down control command (PDWCMD)

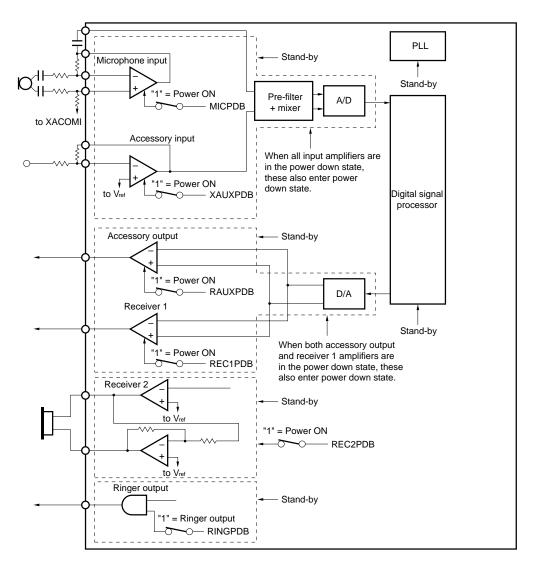
An outline diagram of power down control is shown in Figure 2-5.



Figure 2-5 Power Down Control

Re	gister addr	ess			AMPCR						
0	0	0	MICPDB	XAUXPDB	REC1PDB	RAUXPDB	RINGPDB	3			
	Re	gister addr	ess	<u> </u>	·	TXGCR					
0	0	0	1	1	0	REC2PDB	TXAG				
			Power up	command				HE M	X ^{Note}		
0	1	1	1	1	0	_		78H	1EH		
		F	ower dow	n comman	d			HE M	X ^{Note}		
0	1	1	1	0	0	_		70H	0EH		

Note M: HEX value with MSB first L: HEX value with LSB first



Caution MICPDB and XAUXPDB cannot enter the power up state at the same time (MICPDB = XAUXPDB = "1").



(3) Input/output amplifier control register (AMPCR)

This is a 5-bit register for power up/down control of each input/output amplifier (not including receiver amplifier 2), and for ringer output ON/OFF control.

Remark For information on power up/down control of receiver amplifier 2, refer to 4.1.1 Voice Send Analog Gain/
Receiver Amplifier 2 Control Register (TXGCR).

Register address **AMPCR** D7 D5 D4 D3 D2 D1 D0 D6 0 0 MICPDB | XAUXPDB | REC1PDB | RAUXPDB | RINGPDB MICPDB Microphone amplifier power control Power down 0 1 Power up XAUXPDB Accessory input amplifier power control 0 Power down 1 Power up REC1PDB Receiver amplifier 1 power control Power down 0 1 Power up RAUXPDB Accessory output amplifier power control 0 Power down Power up 1 RINGPDB Ringer output control Sets output at low level. 0 1 Output enable

Figure 2-6 Input/Output Amplifier Control Register

- **Remarks 1.** In the stand-by mode, all amplifiers enter the power down state regardless of input/output control register settings. However, register contents are held unless reset or written, so when the stand-by mode is cleared by power up command, the command prior to the stand-by mode is resumed.
 - 2. The microphone and accessory amplifiers cannot enter the power up (D4 = D3 = "1") state at the same time.



Table 2-4 Function Specification by Input/Output Amplifier Control Register

Register address		ldress		Α	MPC	R		Microphone	Accessory	Receiver	Accessory		HEX	Note	
D7	D6	D5	D4	D3	D2	D1	D0		input amplifier	amplifier 1	output amplifier	Ringer output	М	L	Remarks
0	0	0	0	0	0	0	0	Х	Х	Х	Х	Stop	00H	00H	At reset
			0	0	0	0	1	Х	Х	Х	Х	Output	01H	80H	
			0	0	0	1	0	Х	Х	Х	0	Stop	02H	40H	
			0	0	0	1	1	Х	Х	Х	0	Output	03H	C0H	
			0	0	1	0	0	Х	Х	0	Х	Stop	04H	20H	
			0	0	1	0	1	X	Х	0	X	Output	05H	A0H	
			0	0	1	1	0	X	Х	0	0	Stop	06H	60H	
			0	0	1	1	1	Х	X	0	0	Output	07H	E0H	
			0	1	0	0	0	Х	0	Χ	X	Stop	08H	10H	
			0	1	0	0	1	Х	0	Χ	X	Output	09H	90H	
			0	1	0	1	0	Х	0	X	0	Stop	0AH	50H	
			0	1	0	1	1	Х	0	Χ	0	Output	0BH	D0H	
			0	1	1	0	0	Х	0	0	X	Stop	0CH	30H	
			0	1	1	0	1	Х	0	0	X	Output	0DH	вон	
			0	1	1	1	0	Х	0	0	0	Stop	0EH	70H	
			0	1	1	1	1	Х	0	0	0	Output	0FH	F0H	
			1	0	0	0	0	0	X	X	X	Stop	10H	08H	
			1	0	0	0	1	0	X	Χ	X	Output	11H	88H	
			1	0	0	1	0	0	X	X	0	Stop	12H	48H	
			1	0	0	1	1	0	X	Χ	0	Output	13H	C8H	
			1	0	1	0	0	0	X	0	X	Stop	14H	28H	
			1	0	1	0	1	0	X	0	X	Output	15H	A8H	
			1	0	1	1	0	0	X	0	0	Stop	16H	68H	
			1	0	1	1	1	0	X	0	0	Output	17H	E8H	

Note M: HEX value with MSB first L: HEX value with LSB first

Remark O: Power up X: Power down



(4) Power up/down command (PUPCMD/PDWCMD)

The stand-by mode is set and cleared by the following two special commands. When resetting, the stand-by mode is set.

Figure 2-7 Power Down Command (Sets to stand-by mode)

PDWCMD

D7	D6	D5	D4	D3	D2	D1	D0
0	1	1	1	0	0	Х	Х

Remark X: Don't Care

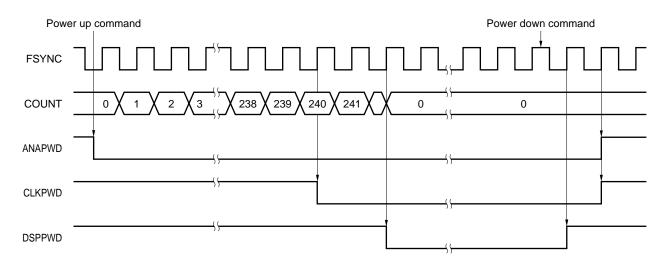
Figure 2-8 Power Up Command (Clears stand-by mode)

PUPCMD

D7	D6	D5	D4	D3	D2	D1	D0	
0	1	1	1	1	0	Х	Х	

Remark X: Don't Care

Power up/down timing



Remarks COUNT: Internal counter (counts with an 8-kHz internal clock)

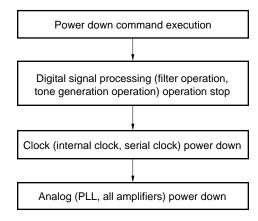
ANAPWD: Analog power down (power down when high) CLKPWD: Clock power down (power down when high)

DSPPWD: Signal processing power down (power down when high)

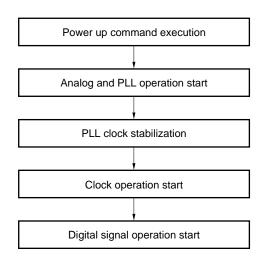


(5) Power up/down sequence

(a) Power down sequence



(b) Power up sequence



Remarks 1. The DSP interface serial input/output operation does not stop or start when switching to power up/down.

- 2. Rising time from standby mode to normal operation mode is about 30.5 ms after execution of the power up command.
- **3.** FSYNC can be stopped at power down. However, input of the FSYNC clock is necessary during operation and in the above sequence.



2.1.7 Microcontroller Interface

The μ PD9930 can control internal functions by microcontroller command. A clock synchronous serial I/O is incorporated to receive command.

A clocked serial interface is provided to receive microcontroller commands. A microcontroller connection example is shown in **Figure 2-9**. 8-bit length data is received by the serial clock (MCLK), serial input (MDAT), and strobe input (MSTR) lines^{Note}.

The timing chart is shown in **Figure 2-10**. By reading data to the internal shift register and setting MSTR to high level at the MCLK rising point, it is latched to the internal control register. Data transfer must be made with LSB first.

Note When 8 bits or more (9 MCLK clocks or more) data is input, the last 8-bit which is input immediately before the active edge of MSTR is recognized as a control command.

Microcontroller

Serial I/O

SO

SCK

PORT

Microcontroller I/F

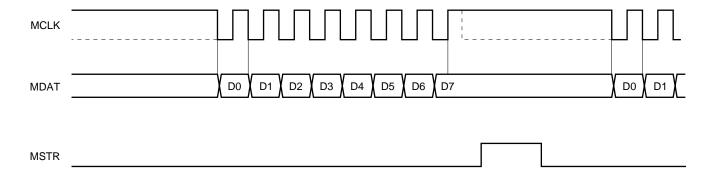
MDAT

MCLK

MSTR

Figure 2-9 Example of Connection with Microcontroller

Figure 2-10 Microcontroller Interface Timing Chart

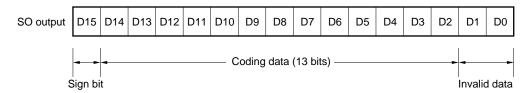




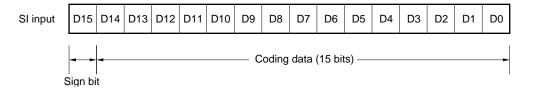
2.1.8 DSP Interface

A clock synchronous serial I/O is built-in to exchange voice send/receive coding data with an external DSP. 16-bit data is transferred at 8 kHz by the serial clock (SCLK = 256 kHz), serial input (SI), serial output (SO), and enable output (SEN) lines. The REQB is a terminal for allowing/inhibiting data transmission. There are two modes for data input and output timing, and either can be selected by the DSPSEL terminal. Select the mode matching the DSP serial interface input/output timing. Data format is as follows: Both SO output and SI input are in 2's complement format with MSB first.

Figure 2-11 Data Format in DSP Interface



Remark A full code is output when the SO pin is +3.17 dBm0 (A/D 1.2 V_{P-P}).



Remark When a full code is input to the SI pin, the accessory output is 1.2 V_{P-P}.

Table 2-5 DSP Input/Output Timing Mode Selection

Pin input	Mode			
DSPSEL	Iviode			
Н	MODE1			
L	MODE2			

Table 2-6 Allowing Data Transmission

REQB pin Input	Data Transmission
L	Data transmission is allowed. Enable signal (SEN) is output at rising edge of FSYNC (8 kHz), and data input/output is started.
Н	Enable signal is not output and data are not input or output.



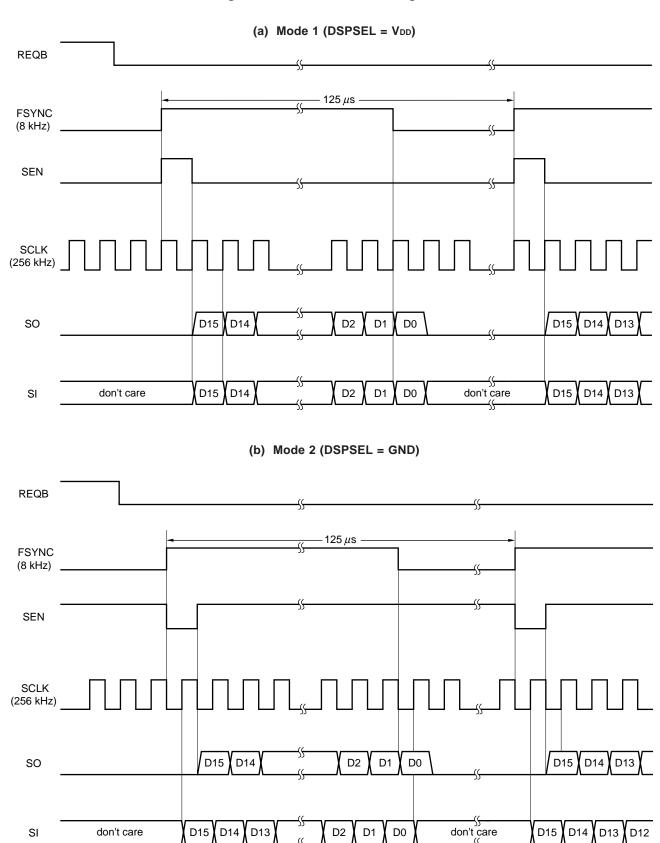
DSP $\mu\, \mathrm{PD9930}$ Serial I/O DSP I/F SCLK SCK **FSYNC** - 8 kHz enable SEN SI SO SO SI PORT REQB V_{DD} - $\mathsf{DSPSEL}^{\mathsf{Note}}$

Figure 2-12 Example of Connection with DSP (Mode 1)

Note When using with mode 2, connect DSPSEL to GND.



Figure 2-13 DSP Interface Timing Chart





2.1.9 DAI (Digital Audio Interface)

Has a on-chip circuit enabling DAI functions specified in GSM11.10. The receive system has a on-chip LPF only. If a BPF is necessary, it should be mounted externally. System configuration at the time of DAI test mode is shown in **Figure 2-15**. The DAI terminal is connected to the system simulator via the pin 25 DSUB socket. The test mode can be selected by terminals TC1 or TC2, or by microcontroller command. DAI mode should be set after completing power-up operation (30.5 ms after executing power-up command).

When changing the modes from DAI to normal, either of the following operations should be executed.

- After specifying normal mode, input the DAI reset signal (DRSTB = low).
- Input reset signal (RESETB = low).

When specifying by command, test control register mode specification bits (ITC1, ITC2) are used (Refer to 4.4.1 Test Control Register (TSTCR).).

Timing for each mode is shown in Figures 2-16 through 2-20.

For operation at the time of each mode, refer to Figure 4-13 Test Mode Operation.

TC2 TC1 Test mode Function (ITC2) (ITC1) specification 0 Normal operation^{Note} 0 Normal operation. This mode is set at system reset (when RESETB = low) regardless of status of TC1 and TC2. Outputs data input from DI pin to DSP (speech encoder) from SO pin. Speech encoder Input is started at rising edge of first FSYNC (8-kHz external clock input) after test mode execution of mode specification, and outputting data to DSP is started at next rising edge of FSYNC. 1 Speech decoder Outputs speech decoder output data input from SI pin from DO pin. test mode Inputting data from DSP is started at rising edge of first FSYNC (8-kHz external clock input) after execution of mode specification, and data is output from DO pin at next rising edge of FSYNC. Acoustic device, A/D, Outputs audio data converted into digital signal from DO pin. 1 D/A test mode Also inputs audio data input from DI pin to D/A converter. Inputting/outputting data is started at rising edge of first FSYNC (8-kHz external clock input) after execution of mode specification. At this time, clock output to DSP (SCLK) is stopped.

Table 2-7 DAI Test Mode Specification

Note In the normal mode, do not set DRSTB to low level (during low period, serial interface with DSP is disabled).

As well, set the output pins of driver IC to high-impedance state, because DRSTB input pin is connected with a pull-up resistor.

Remark Analog loop back mode and DAI test mode cannot be specified at the same time.

DAI test mode is set with TC1, TC2 (or ITC1, ITC2) and DRSTB pins. DAI test mode is entered at the rising edge of the DRSTB signal when both TC1 and TC2 pins (or ITC1 and ITC2 pins) are set as shown in **Figure 2-14**.



Figure 2-14 Latch Timing of TC1, TC2 (or ITC1, ITC2)

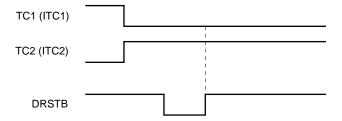
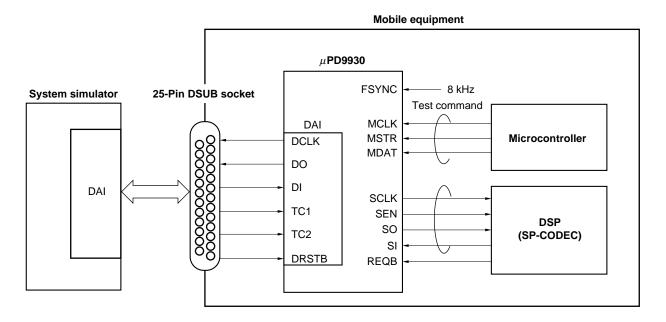


Figure 2-15 Example of System Configuration at Time of DAI Test Mode



Remark In the acoustic device test mode, REQB is ignored (both high and low levels). When DSPSEL = V_{DD} (mode 1), SCLK and SEN are fixed to low, and when DSPSEL = GND (mode 2), fixed to high.

Figure 2-16 Speech Encoder Test Mode (DSP Interface = MODE 1) (TC1 = 1, TC2 = 0)

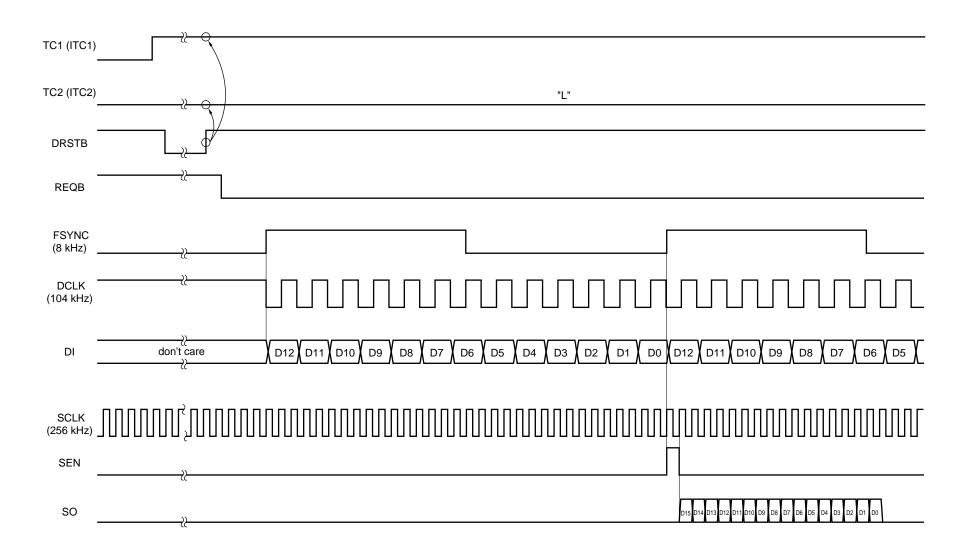


Figure 2-17 Speech Encoder Test Mode (DSP Interface = Mode 2) (TC1 = 1, TC2 = 0)

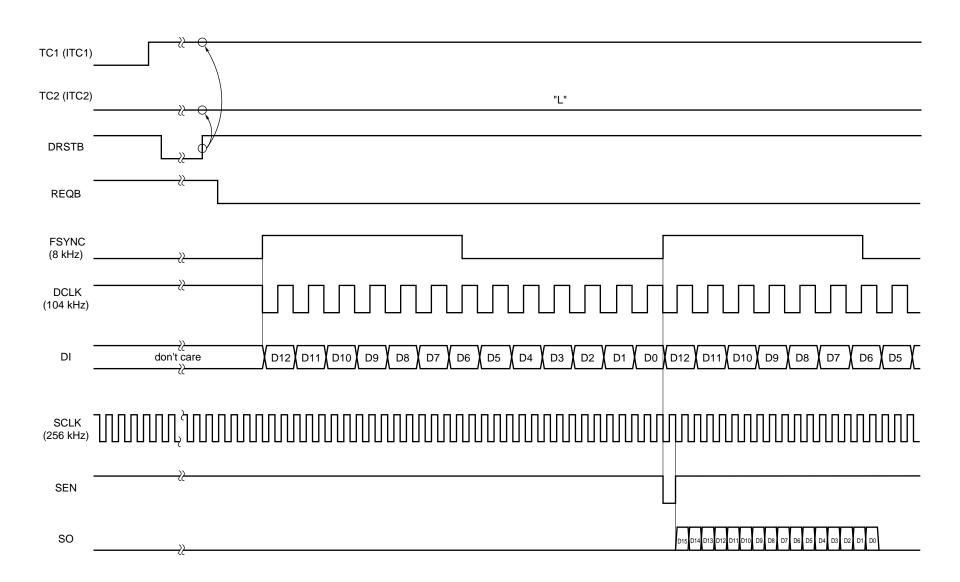
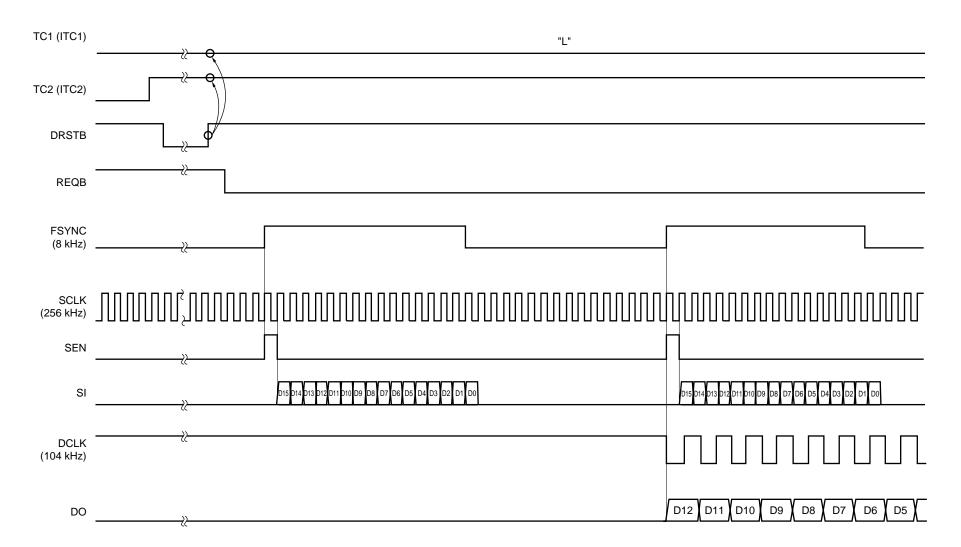


Figure 2-18 Speech Decoder Test Mode (DSP Interface = Mode 1) (TC1 = 0, TC2 = 1)





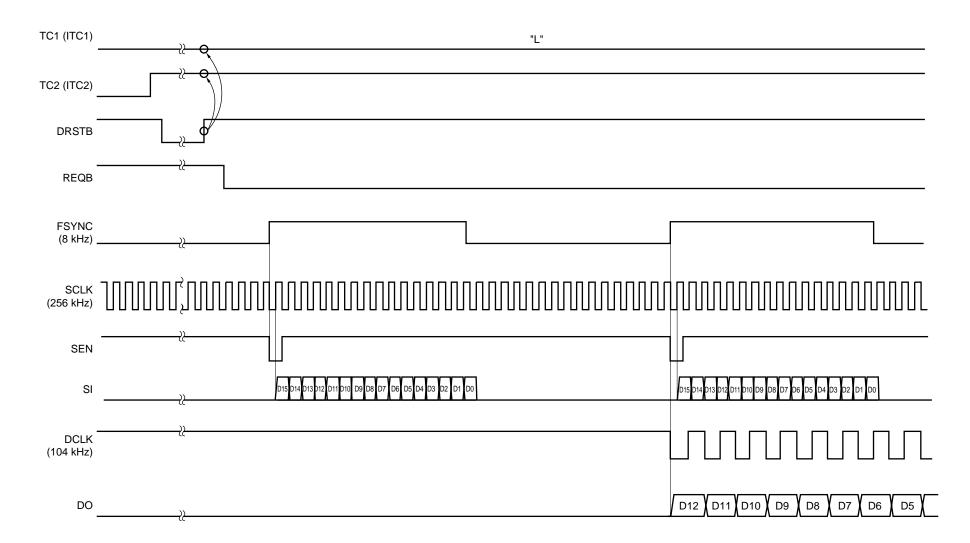
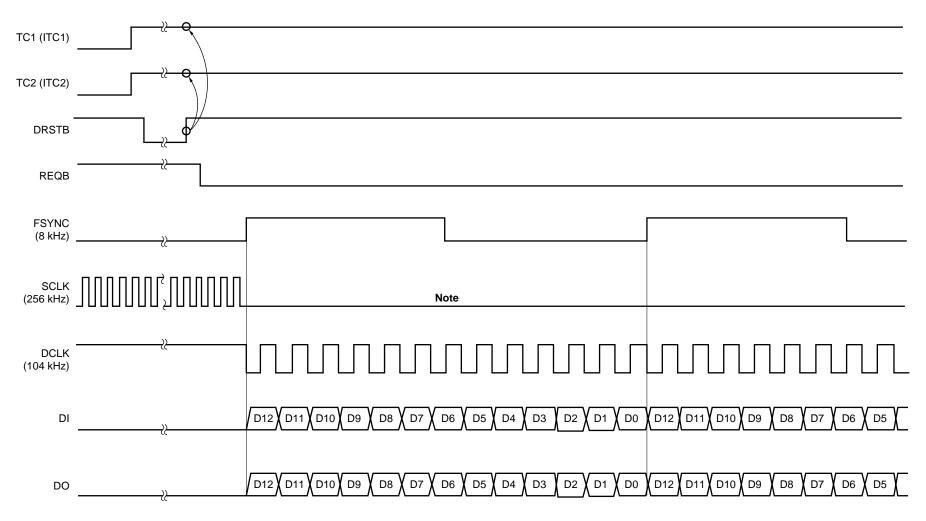


Figure 2-20 Acoustic Device Test Mode (DSP Interface = Mode 1) (TC1 = 1, TC2 = 1)



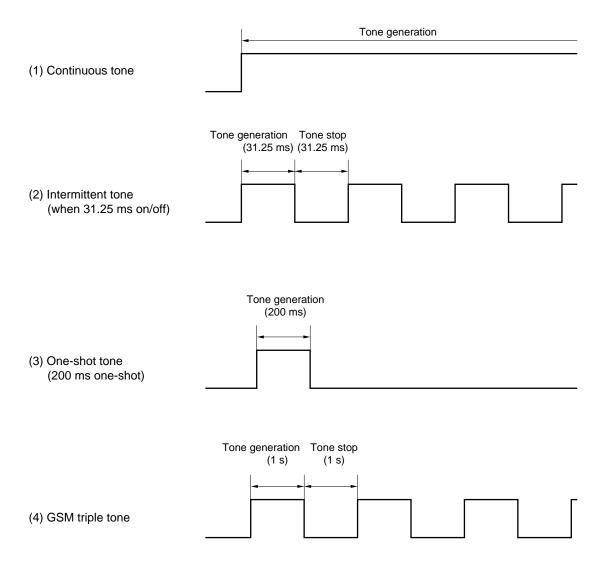
Note In DSP Interface = Mode 2, SCLK is fixed to high.



3. TONE INTERVAL OUTPUT FUNCTION (TIMER TERMINAL)

When a tone is generated, an interval signal that indicates the tone intermittent state is output. The function is used, for example, to make the LED blink in synchronization with the ringer tone.

Figure 3-1 Tone Interval Output Waveform





★ 4. INTERNAL CONTROL FUNCTIONS

The μ PD9930 can control internal functions by commands from a microcontroller. Commands consist of 8-bit data (D7 to D0) consisting of register address and setting data, and are written in the following internal registers.

	Register name	Control
(1)	Voice send analog gain/receiver amplifier 2 control register (TXGCR)	Voice send/receive gain control
(2)	Voice receive analog gain control register (RXGCR)	
(3)	Voice send/receive digital gain control register (DGGSR)	
(4)	Digital signal processing control register (DSPCR)	Digital input/output control
(5)	Tone frequency selection register (FRQSR)	Tone control
(6)	Expanded tone register (EXPR1/EXPR2)	
(7)	Tone control register (TONCR)	
(8)	Tone gain control register (TNGCR)	
(9)	Input/output amplifier control register (AMPCR)	Power up/down control
(10)	Power up control command (PUPCMD)	
(11)	Power down control command (PDWCMD)	
(12)	Test control register (TSTCR)	Test mode control

Remarks 1. In the case of registers (1), (2), and (9) to (11), written contents are executed instantly.

- 2. For registers (3) to (8) and (12), since fetch execution is made by the internal clock (125 μ s interval), keep 125 μ s or more interval for write-in to the same register.
 - If the write-in to the same register is executed continuously, the previous command may be ignored.
- **3.** Even when in the stand-by mode, write-in to each internal register is possible (can be held), but the command written in the register is executed only after clearing the stand-by mode.

4.1 SEND/RECEIVE GAIN CONTROL

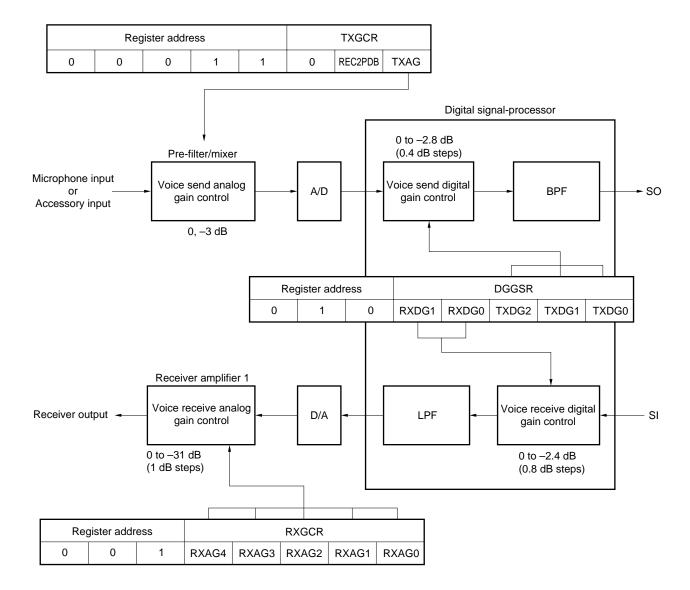
An outline of send/receive gain control is shown in Figure 4-1.

With the μPD9930 , the following send and receive gain control is possible.

	Send/receive gain control	Register used				
Voice send gain control	Pre-filter analog gain adjustment (0, -3 dB)	Voice send analog gain/receiver amplifier 2 control register (TXGCR)				
	Digital gain fine adjustment (0 to -2.8 dB, 0.4 dB steps)	Voice send/receive digital gain control register (DGGSR)				
Voice receive gain control	Receiver amplifier 1 analog gain adjustment (volume control) (0 to -31 dB, 1 dB steps)	Voice receive analog gain control register (RXGCR)				
	Digital gain fine adjustment (0 to -2.4 dB, 0.8 dB steps)	Voice send/receive digital gain control register (DGGSR)				



Figure 4-1 Send/Receive Gain Control





4.1.1 Voice Send Analog Gain/Receiver Amplifier 2 Control Register (TXGCR)

This register controls pre-filter gain. It also controls receiver amplifier 2 power up/down as shown in Table 4-1 (Refer to **2.1.6 Power Up/Down Control**).

When power is down, the contents of the register area retained. After power is up, control continues as before power was down.

Figure 4-2 Voice Send Analog Gain/Receiver Amplifier 2 Control Register

		Re		TXGCR						
	D7	D6	D5	D4	D3	D2	D1	D0		
	0	0	0	1	1	0	REC2PDB	TXAG		
REC2PDB	Receiver am	plifier 2 pov	wer up/dow	n specifica	tion					
0	Power down									
1	Power up									
TXAG	Pre-filter ana	olog gain sp	ecification							
0	Sets to 0 dB									
1	Sets to -3 dB									

Table 4-1 Function Specification by Send Analog Gain/Receiver Amplifier 2 Control Register

R	Register address TXGCR			egister address TXGCR			XGC	R	Desciver emplifier 2	Voice and analog gain	HE	(Note	Damada
D7	D6	D5	D4	D3	D2	D1	D0	Receiver amplifier 2	Voice send analog gain	М	L	Remarks	
0	0	0	1	1	0	0	0	Power down	0 dB	18H	18H	At reset	
					0	0	1	Power down	−3 dB	19H	98H		
					0	1	0	Power up	0 dB	1AH	58H		
					0	1	1	Power up	−3 dB	1BH	D8H		

Note M: HEX value with MSB first L: HEX value with LSB first



4.1.2 Voice Receive Analog Gain Control Register (RXGCR)

00000 to 11111 0 to -31 dB (1 dB steps)

This is a 5-bit register for controlling the analog gain (volume) of receiver amplifier 1.

Figure 4-3 Voice Receive Analog Gain Control Register

	Re	gister addr	ess	RXGCR							
	D7 D6		D5	D4	D3	D2	D1	D0			
	0	0	1	RXAG4	RXAG3	RXAG2	RXAG1	RXAG0			
RXAG4 to RXAG	Receive	er amplifier	1 gain spe	cification		-					



Table 4-2 Function Specifications by Voice Receive Analog Gain Control Register

Register address			R	XGC	R			HEXNote		Damada	
D7	D6	D5	D4	D3	D2	D1	D0	Voice receive analog gain	М	L	Remarks
0	0	1	0	0	0	0	0	0 dB	20H	04H	
			0	0	0	0	1	-1 dB	21H	84H	
			0	0	0	1	0	−2 dB	22H	44H	
			0	0	0	1	1	−3 dB	23H	C4H	
			0	0	1	0	0	–4 dB	24H	24H	
			0	0	1	0	1	–5 dB	25H	A4H	
			0	0	1	1	0	−6 dB	26H	64H	
			0	0	1	1	1	−7 dB	27H	E4H	
			0	1	0	0	0	-8 dB	28H	14H	
			0	1	0	0	1	−9 dB	29H	94H	
			0	1	0	1	0	-10 dB	2AH	54H	
			0	1	0	1	1	-11 dB	2BH	D4H	
			0	1	1	0	0	−12 dB	2CH	34H	
			0	1	1	0	1	-13 dB	2DH	В4Н	
			0	1	1	1	0	-14 dB	2EH	74H	
			0	1	1	1	1	-15 dB	2FH	F4H	
			1	0	0	0	0	-16 dB	30H	0CH	
			1	0	0	0	1	-17 dB	31H	8CH	
			1	0	0	1	0	-18 dB	32H	4CH	
			1	0	0	1	1	-19 dB	33H	ССН	
			1	0	1	0	0	-20 dB	34H	2CH	
			1	0	1	0	1	-21 dB	35H	ACH	
			1	0	1	1	0	-22 dB	36H	6CH	
			1	0	1	1	1	-23 dB	37H	ECH	
			1	1	0	0	0	-24 dB	38H	1CH	
			1	1	0	0	1	–25 dB	39H	9CH	
			1	1	0	1	0	-26 dB	ЗАН	5CH	
			1	1	0	1	1	-27 dB	звн	DCH	
			1	1	1	0	0	–28 dB	зсн	3СН	
			1	1	1	0	1	-29 dB	3DH	всн	
			1	1	1	1	0	-30 dB	3EH	7CH	
			1	1	1	1	1	-31 dB	3FH	FCH	At reset

Note M: HEX value with MSB first L: HEX value with LSB first



4.1.3 Voice Send/Receive Digital Gain Control Register (DGGSR)

This is a 5-bit register for adjusting the gain of the digital signal processor. The gain of the send system and receive system can be fine-adjusted independently.

Figure 4-4 Send/Receive Digital Gain Control Register

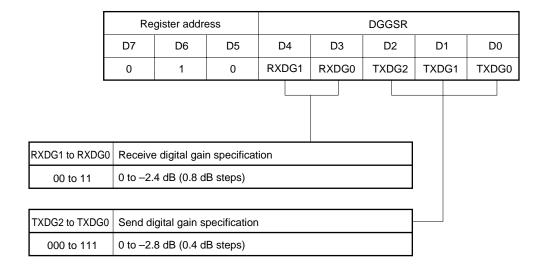




Table 4-3 Function Specifications by Voice Send/Receive Digital Gain Control Register

Register address			D	GGS	R		Voice receive	Voice send	HEX	Note	Damada	
D7	D6	D5	D4	D3	D2	D1	D0	digital gain	digital gain	М	L	Remarks
0	1	0	0	0	0	0	0	0 dB	0 dB	40H	02H	At reset
			0	0	0	0	1	0 dB	-0.4 dB	41H	82H	
			0	0	0	1	0	0 dB	-0.8 dB	42H	42H	
			0	0	0	1	1	0 dB	−1.2 dB	43H	C2H	
			0	0	1	0	0	0 dB	-1.6 dB	44H	22H	
			0	0	1	0	1	0 dB	-2.0 dB	45H	A2H	
			0	0	1	1	0	0 dB	-2.4 dB	46H	62H	
			0	0	1	1	1	0 dB	-2.8 dB	47H	E2H	
			0	1	0	0	0	-0.8 dB	0 dB	48H	12H	
			0	1	0	0	1	-0.8 dB	-0.4 dB	49H	92H	
			0	1	0	1	0	-0.8 dB	-0.8 dB	4AH	52H	
			0	1	0	1	1	-0.8 dB	−1.2 dB	4BH	D2H	
			0	1	1	0	0	-0.8 dB	-1.6 dB	4CH	32H	
			0	1	1	0	1	-0.8 dB	-2.0 dB	4DH	В2Н	
			0	1	1	1	0	-0.8 dB	-2.4 dB	4EH	72H	
			0	1	1	1	1	-0.8 dB	–2.8 dB	4FH	F2H	
			1	0	0	0	0	−1.6 dB	0 dB	50H	0AH	
			1	0	0	0	1	−1.6 dB	-0.4 dB	51H	8AH	
			1	0	0	1	0	−1.6 dB	-0.8 dB	52H	4AH	
			1	0	0	1	1	-1.6 dB	-1.2 dB	53H	CAH	
			1	0	1	0	0	−1.6 dB	–1.6 dB	54H	2AH	
			1	0	1	0	1	-1.6 dB	-2.0 dB	55H	AAH	
			1	0	1	1	0	-1.6 dB	-2.4 dB	56H	6AH	
			1	0	1	1	1	−1.6 dB	–2.8 dB	57H	EAH	
			1	1	0	0	0	-2.4 dB	0 dB	58H	1AH	
			1	1	0	0	1	-2.4 dB	-0.4 dB	59H	9AH	
			1	1	0	1	0	-2.4 dB	-0.8 dB	5AH	5AH	
			1	1	0	1	1	-2.4 dB	–1.2 dB	5BH	DAH	
			1	1	1	0	0	-2.4 dB	-1.6 dB	5CH	ЗАН	
			1	1	1	0	1	-2.4 dB	-2.0 dB	5DH	ВАН	
			1	1	1	1	0	-2.4 dB	-2.4 dB	5EH	7AH	
			1	1	1	1	1	-2.4 dB	-2.8 dB	5FH	FAH	

Note M: HEX value with MSB first L: HEX value with LSB first



4.2 DIGITAL INPUT/OUTPUT CONTROL

An outline of digital input/output control is shown in Figure 4-5.

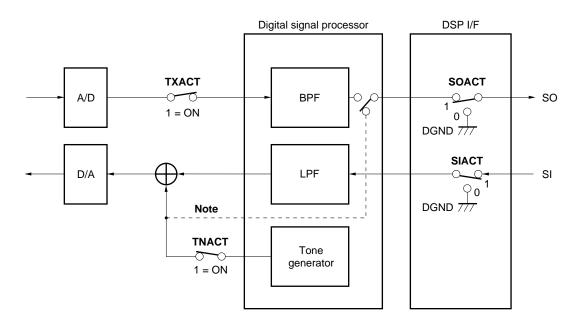
The μ PD9930 can control input and output of the digital signal processor as follows.

Digital input/output control	Registers used
Voice send data BPF operation processing execution/stop	
Connection and disconnection to tone output Voice send/ receive system	Digital signal processing control register (DSPCR)
Serial output terminal (SO) control	
Serial input terminal (SI) control	

Caution You must not connect nor disconnect tone output voice send/receive system in the tone operation. It causes malfunction.

Figure 4-5 Digital Input/Output Control

	Register	address		DSPCR			
0	1	1	0	TXACT	TNACT	SOACT	SIACT



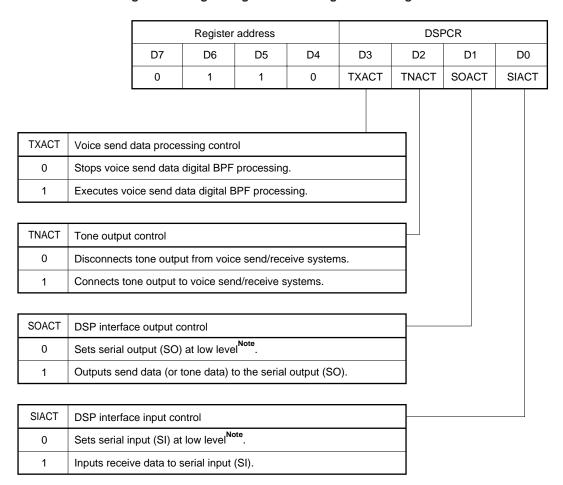
Note Connected when TXACT = 0 and TNACT = 1.



4.2.1 Digital Signal Processing Control Register (DSPCR)

This is a 4-bit register for controlling digital signal processor input/output.

Figure 4-6 Digital Signal Processing Control Register



Note Test Control Register can set serial input/output terminal at low level, too (refer to 4.4.1 Test Control Register (TSTCR)).

Caution Before specification of SOACT bit, be sure to write "0" for SIOOFF bit of Test Control Register.

If "0" isn't written for SIOOFF bit, serial output terminal is set at low level, regardless of SOACT bit.



Table 4-4 Function Specification by Digital Signal Processing Control Register

Re	giste	r add	ress		DSF	PCR			0	HEX	(Note	
D7	D6	D5	D4	D3	D2	D1	D0	Serial output control Control of output to D/A		М	L	Remarks
0	1	1	0	0	0	0	0	Note 2	Note 3	60H	06H	At reset
				0	0	0	1	Note 2	Voice receive signal output	61H	86H	
	0 0 1 0		0	Inhibiting	command	_	_					
	0 0 1			1	1	Inhibiting	command	_	_			
				0	1	0	0	Note 2 Tone output		64H	26H	
				0	1	0	1	Note 2	Voice receive signal + tone output	65H	A6H	
				0	1	1	0	Tone output Tone output		66H	66H	
				0	1	1	1	Tone output	Voice receive signal + tone output	67H	E6H	
				1	0	0	0	Inhibiting	command	_	_	
				1	0	0	1	Inhibiting	command	_	_	
				1	0	1	0	Voice send signal output	Note 3	6AH	56H	
				1	0	1	1	Voice send signal output	Voice receive signal output	6BH	D6H	
				1	1	0	0	Inhibiting command		_	_	
				1	1	0	1	Inhibiting command		_	_	
				1	1	1	0	Voice send signal output Tone output			76H	
				1	1	1	1	Voice send signal output	Voice receive signal + tone output	6FH	F6H	

Notes 1. M: HEX value with MSB first

L: HEX value with LSB first

- 2. Stops voice send data processing and serial output.
- 3. Stops voice receive data serial input and tone output.



4.3 TONE CONTROL

An outline diagram of the tone generator is shown in **Figure 4-7**. Tone generation is by the tone 1 oscillation circuit and the tone 2 oscillation circuit.

The tone 1 oscillation circuit generates high group frequency for DTMF and four types of single tones (tone 1 frequency).

The tone 2 oscillation circuit generates low group frequency (tone 2 frequency) for DTMF. Dual tone is output by adding tone 1 frequency.

In addition to registered tones, other frequencies can be registered. Also, GSM triple tone can be generated by special command. Examples of tone generation are shown in **Figure 4-8**.

Tone control items are shown below.

		Tone control	Registers used
Tone frequency	Registered tone	Specification of DTMF	Tone frequency selection register
		Single tone: 400 Hz, 425 Hz, 2 kHz, 2.6 kHz	(FRQSR)
		Selection of GSM triple tone	Tone control register (TONCR)
	User registration tone	Registration of desired tone in 0.3 to 3.4 kHz range.	Tone frequency selection register (FRQSR)
		(Single tone, dual tone)	Expanded tone register 1 (EXPR1)
			Expanded tone register 2 (EXPR2)
Generation pattern	Registered pattern	31.25 ms intermittence, 200 ms intermittence, 250 ms intermittence, 500 ms intermittence, 1s intermittence, 200 ms one-shot tone	Tone control register (TONCR)
	Desired pattern	Interrupted at desired interval by START/STOP command	
Gain	Control of tone ou 0 to -30 dB (1 dB	utput gain 8 steps), –38.5 dB	Tone gain control register (TNGCR)

Register address **FRQSR** 0 FRQSEL4 FRQSEL3 FRQSEL2 FRQSEL1 FRQSEL0 Register address **TNGCR** Tone 1 oscillation circuit TNGAIN4 TNGAIN3 TNGAIN2 TNGAIN1 TNGAIN0 1 Tone 1 frequency 1209 Hz 400 Hz 1336 Hz 425 Hz 0 to -30 dB 1477 Hz 2000 Hz (1-dB steps) 1633 Hz 2600 Hz 3.1 dBm0 -38.5 dB LPF output (receive signal) (Only sign code)

Ringer output Expanded tone register 1 Expanded tone 1 frequency TNACTNote ► To D/A START/ STOP Serial output Tone 2 oscillation circuit Timer output Tone 2 frequency Tone interval generation 697 Hz 770 Hz Note Digital signal processing control 852 Hz 941 Hz register bit 2 (Refer to Figure 4-6). 3.1 dBm0 Expanded tone 2 frequency Expanded tone register 2

TONCR

TNP1

TNP0

START/

STOP

Register address

0

1

1

TNMODE

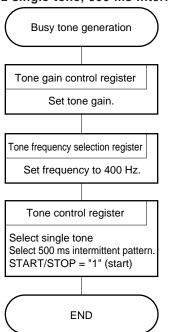
TNP2

Figure 4-7 Tone Control

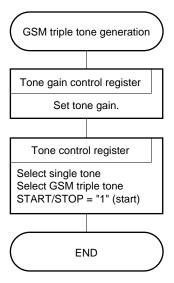


Figure 4-8 Tone Generation Examples

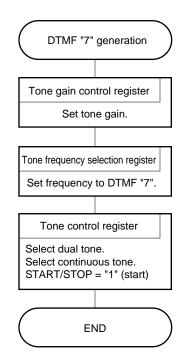
(a) When generating a busy tone (400 Hz single tone, 500 ms intermittence)



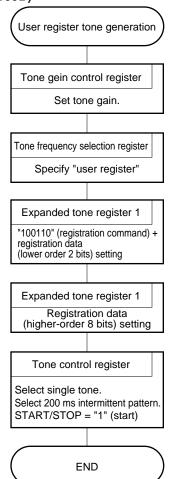
(c) When generating GSM triple tone



(b) When generating DTMF "7" with continuous tone



(d) When generating 200 ms intermittent user register tone (480 Hz single tone; coefficient = 0111011100B)





4.3.1 Tone Frequency Selection Register (FRQSR)

This is a 5-bit register for specifying tone 1 (high group frequency for DTMF and four types of single tones) and tone 2 (low group frequency for DTMF) frequency combinations.

Figure 4-9 Tone Frequency Selection Register

	Re	FRQSR							
	D7 D6 D5			D4		D3	D2	D1	D0
	1 0 0			FRQSE	L4 I	FRQSEL3	FRQSEL2	FRQSEL1	FRQSELO
		•	•						
FRQSEL4 to FRQSEL0 Tone frequency selection									
00000 to 10100	Refer to T	able 4-5 F	unction S	pecificat	ion	by Tone I	Frequency	Selection	Register.

Write operation in this register is instantaneously executed and retained when a command is received, but change of tone generation or generating tone is executed only when "1" is written for START/STOP control bit of the tone control register (refer to Figure 4-11 Tone Control Register).

When a user registration tone is selected, the tone specified by the expanded tone register (refer to Figure 4-10 Expanded Tone Frequency Registration Procedure) is generated.

Caution Do not input a command that sets a tone oscillation frequency after inputting a tone oscillation command (writing "1" to the START/STOP control bit of the tone control register).



Table 4-5 Function Specification by Tone Frequency Selection Register

Regi	ster ac	ddress		F	RQS	R					HEX	Note 1	
D7	D6	D5	D4	D3	D2	D1	D0	DTMF function	Tone 1 frequency	Tone 2 frequency	М	L	Remarks
1	0	0	0	0	0	0	0	DTMF "1"	1209 Hz	697 Hz	80H	01H	
			0	0	0	0	1	DTMF "2"	1336 Hz	697 Hz	81H	81H	
			0	0	0	1	0	DTMF "3"	1477 Hz	697 Hz	82H	41H	
			0	0	0	1	1	DTMF "A"	1633 Hz	697 Hz	83H	C1H	
			0	0	1	0	0	DTMF "4"	1209 Hz	770 Hz	84H	21H	
			0	0	1	0	1	DTMF "5"	1336 Hz	770 Hz	85H	A1H	
			0	0	1	1	0	DTMF "6"	1477 Hz	770 Hz	86H	61H	
			0	0	1	1	1	DTMF "B"	1633 Hz	770 Hz	87H	E1H	
			0	1	0	0	0	DTMF "7"	1209 Hz	852 Hz	88H	11H	
			0	1	0	0	1	DTMF "8"	1336 Hz	852 Hz	89H	91H	
			0	1	0	1	0	DTMF "9"	1477 Hz	852 Hz	8AH	51H	
			0	1	0	1	1	DTMF "C"	1633 Hz	852 Hz	8BH	D1H	
			0	1	1	0	0	DTMF "*"	1209 Hz 941 Hz		8CH	31H	
			0	1	1	0	1	DTMF "0"	1336 Hz	941 Hz	8DH	В1Н	
			0	1	1	1	0	DTMF "#"	1477 Hz	941 Hz	8EH	71H	
			0	1	1	1	1	DTMF "D"	1633 Hz	941 Hz	8FH	F1H	
			1	0	0	0	0		400 Hz ^{Note 2}	Indefinite value	90H	09H	
			1	0	0	0	1		425 Hz ^{Note 2}	Indefinite value	91H	89H	
			1	0	0	1	0		2 kHz ^{Note 2}	Indefinite value	92H	49H	
			1	0	0	1	1		2.6 kHz ^{Note 2}	Indefinite value	93H	С9Н	At reset
			1	0	1	0	0		User registration	User registration	94H	29H	
			1	0	1	0	1		Inhibiting command		_		
			1	0	1	1	0	Inhibiting command				_	
			1	0	1	1	1		Inhibiting command		_	_	

Notes 1. M: HEX value with MSB first

L: HEX value with LSB first

2. This is single tone. When specifying this tone, be sure to specify the tone control register in the single tone mode (refer to Figure 4-11 Tone Control Register).

Remark For DTMF tone generation, specify the tone control register in the dual tone mode (refer to **Figure 4-11 Tone Control Register**). If the register is specified in the single tone mode, only the high group tone (tone 1 frequency) is generated.



4.3.2 Expanded Tone Registers (EXPR1, EXPR2)

(1) Expanded Tone Frequency Registration Procedure

The μ PD9930 can register desired tone frequencies (expanded tone frequencies) in 0.3 to 3.4 kHz range. Expanded tone register 1 (EXPR1) is for registering expanded tone 1 frequency (high group frequency for DTMF and single tone). Expanded tone register 2 (EXPR2) is for registering expanded tone 2 frequency (low frequency for DTMF). The frequency must be specified by 10-bit coefficient (2's complement).

Registration of single tone is done with EXPR1 (single-tone generation is impossible by EXPR2) (refer to **Figure 4-10 (a)**).

When registering dual tone, set high group in EXPR1 and low group in EXPR2.

Write operation in this register can be executed by continuously writing the expanded tone registration command and expanded tone data command (refer to **Figure 4-10**).

Once registered, the frequency is valid until reset or updated.

Figure 4-10 Expanded Tone Frequency Registration Procedure

(a) Expanded tone 1 frequency registration procedure

<1> Set expanded tone 1 registration command in EXPR1.

Expanded tone 1 registration command

EXPR1

D7	D6	D5	D4	D3	D2	D1	D0
1	0	0	1	1	0	EA1	EA0

<2> Set higher-order 8 bits of expanded tone coefficient (expanded tone 1 data command) in EXPR1.

Expanded tone 1 data command

EXPR1

D7	D6	D5	D4	D3	D2	D1	D0
EA9	EA8	EA7	EA6	EA5	EA4	EA3	EA2

Remark EA9 to EA0: Tone 1 frequency 10-bit coefficient

(b) Expanded tone 2 frequency registration procedure

<1> Set expanded tone 2 registration command in EXPR2.

Expanded tone 2 registration command

EXPR2

D7	D6	D5	D4	D3	D2	D1	D0
1	0	0	1	1	1	EB1	EB0

<2> Set higher-order 8 bits of expanded tone coefficient (expanded tone 2 data command) in EXPR2.

Expanded tone 2 data command

EXPR2

D7	D6	D5	D4	D3	D2	D1	D0
EB9	EB8	EB7	EB6	EB5	EB4	EB3	EB2

Remark EB9 to EB0: Tone 2 frequency 10-bit coefficient

Caution After executing the expanded tone registration command, the next command is written as expanded tone data, so continuously execute the expanded tone data command.



(2) Expanded Tone Data Determination Method

The coefficient E of the tone frequency fe (0.3 to 3.4 kHz) to be generated is determined by the following formula.

```
E = COS (2\pi \text{ fe/fs}) fs = 8 kHz
```

Coefficient E: Sign bit 1 bit + 9 bits below the decimal point (Coefficient: 2's complement)

Example When specifying 400 Hz single tone

```
COS (2\pi \times 400/8000) = COS (\pi \times 0.1)
= COS (0.3141592653.....)
= 0.951056516.....
= (0.11110011X) b (Higher-order 9 bits are determined.)
```

Next, the least significant bit is determined.

```
When (0.11110011\underline{0}) b = 0.94921875

2\pi fe' x fs = COS^{-1} (0.94921875) = 0.320052983

fe' = 0.320052983 x fs/(2\pi)

fe' = 407.504115

When (0.11110011\underline{1}) b = 0.951071875

2\pi fe" x fs = COS^{-1} (0.951071875) = 0.314109559

fe" = 0.314109559 x fs/(2\pi)

fe" = 399.524415
```

Since fe" is nearest to 400 Hz, the coefficient to be registered is (0.111100111) b = (1E7) H.

The error of oscillation frequency by rounding 10-bit coefficient is below ± 5 Hz (MAX. at 300 Hz $\rightarrow \pm 1.7$ %) for all frequencies.

```
About \pm 1.67 % near 300 Hz (\pm 5 Hz)
About \pm 1.00 % near 500 Hz (\pm 5 Hz)
About \pm 0.40 % near 1 kHz (\pm 5 Hz)
About \pm 0.25 % near 2 kHz (\pm 5 Hz)
About \pm 0.16 % near 3 kHz (\pm 5 Hz)
```

Coefficient is negative number in fe > 2.0 kHz.



4.3.3 Tone Control Register (TONCR)

This is a 5-bit register for controlling single tone/dual tone specification, generation pattern selection, and generation and stopping.

Register address **TONCR** D2 D7 D6 D5 D4 D3 D1 D0 **START** 1 **TNMODE** TNP2 TNP1 TNP0 1 0 /STOP

Figure 4-11 Tone Control Register

TNMC	TNMODE Single tone/dual tone specification						
0		Sir	ngle ton	e mode	At reset		
1 Dual tone			al tone	mode			
					-		
TNP2	TN	P1	TNP0	Generation pattern selection	า		
				•			

TNP2	TNP1	TNP0	Generation pattern selection	Remarks
0	0	0	Continuous tone generation	At reset
0	0	1	31.25 ms tone, 31.25 ms no tone repeated	
0	1	0	200 ms tone, 200 ms no tone repeated	
0	1	1	250 ms tone, 250 ms no tone repeated	
1	0	0	500 ms tone, 500 ms no tone repeated	
1	0	1	1 s tone, 1s no tone repeated	
1	1	0	GSM triple tone generated Note 1	
1	1	1	200 ms interval tone generated (one shot tone)	

START/STOP	Tone generation/stop control	Remarks
0	Stop ("1" \rightarrow "0", "0" \rightarrow "0" both valid) Note 2	At reset
1	Validation of tone ferquency selection register setting data, start of generation ("1" \to "1", "0" \to "1" both valid)	

Notes 1. 950 Hz tone 333 ms, 1400 Hz tone 333 ms, 1800 Hz tone 333 ms, 1 s no tone repeated.

2. Do not input a command that sets a tone oscillation frequency after inputting a tone oscillation command (writing "1" to the START/STOP control bit of the tone control register).

Remark When the regeneration pattern is specified as "110", it becomes GSM triple tone command, so tone generation forcibly enters single tone mode.

Tone generation and change of a tone that is being generated is executed only when "1" is written for START/STOP control bit (D0 bit) (refer to **Figure 4-11** and **Table 4-6**).



Table 4-6 Function Specification by Tone Control Register

Regi	ster ac	ddress		Т	ONC	R			HE	XNote
D7	D6	D5	D4	D3	D2	D1	D0	Tone control conditions	М	L
1	0	1	Х	Х	Х	Х	0	Tone stop	A0H	05H
			0	0	0	0	1	Continuous single tone generation	A1H	85H
			0	0	0	1	1	31.25 ms intermittent single tone generation	АЗН	C5H
			0	0	1	0	1	200 ms intermittent single tone generation	A5H	A5H
			0	0	1	1	1	250 ms intermittent single tone generation	A7H	E5H
			0	1	0	0	1	500 ms intermittent single tone generation	А9Н	95H
			0	1	0	1	1	1 s intermittent single tone generation	ABH	D5H
			0	1	1	0	1	GSM triple tone generation	ADH	В5Н
			0	1	1	1	1	200 ms one-shot single tone generation	AFH	F5H
			1	0	0	0	1	Continuous dual tone generation	В1Н	8DH
			1	0	0	1	1	31.25 ms intermittent dual tone generation	взн	CDH
			1	0	1	0	1	200 ms intermittent dual tone generation	В5Н	ADH
			1	0	1	1	1	250 ms intermittent dual tone generation	В7Н	EDH
			1	1	0	0	1	500 ms intermittent dual tone generation	В9Н	9DH
			1	1	0	1	1	1 s intermittent dual tone generation	BDH	BDH
			1	1	1	1	1	200 ms one-shot dual tone generation	BFH	FDH

Note M: HEX value with MSB first L: HEX value with LSB first

Remark X: Don't care

4.3.4 Tone Gain Control Register (TNGCR)

This is a 5-bit register for controlling the tone output gain.

Figure 4-12 Tone Gain Control Register

	Re	gister addre	ess	TNGCR								
	D7	D6	D5	D4	D3	D2	D1	D0				
	1	1	1	TNGAIN4	TNGAIN3	TNGAIN2	TNGAIN1	TNGAIN0				
TNGAIN4 to TNGAIN0	nction ster).											
00000 to 11111	0 to -30 dl	B (1 dB ste	ps), –38.5 (



Table 4-7 Function Specification by Tone Gain Control Register

Regis	Register address		TNGCR			R			HEX	(Note	Pomarka
D7	D6	D5	D4	D3	D2	D1	D0	Tone gain	М	L	Remarks
1	1	1	0	0	0	0	0	0 dB	E0H	07H	
			0	0	0	0	1	−1 dB	E1H	87H	
			0	0	0	1	0	−2 dB	E2H	47H	
			0	0	0	1	1	−3 dB	ЕЗН	C7H	
			0	0	1	0	0	−4 dB	E4H	27H	
			0	0	1	0	1	−5 dB	E5H	A7H	
			0	0	1	1	0	−6 dB	E6H	67H	
			0	0	1	1	1	−7 dB	E7H	E7H	
			0	1	0	0	0	-8 dB	E8H	17H	
			0	1	0	0	1	−9 dB	E9H	97H	
			0	1	0	1	0	-10 dB	EAH	57H	
			0	1	0	1	1	-11 dB	EBH	D7H	
			0	1	1	0	0	−12 dB	ECH	37H	
			0	1	1	0	1	-13 dB	EDH	В7Н	
			0	1	1	1	0	-14 dB	EEH	77H	
			0	1	1	1	1	−15 dB	EFH	F7H	
			1	0	0	0	0	-16 dB	F0H	0FH	
			1	0	0	0	1	-17 dB	F1H	8FH	
			1	0	0	1	0	-18 dB	F2H	4FH	
			1	0	0	1	1	-19 dB	F3H	CFH	
			1	0	1	0	0	-20 dB	F4H	2FH	At reset
			1	0	1	0	1	-21 dB	F5H	AFH	
			1	0	1	1	0	−22 dB	F6H	6FH	
			1	0	1	1	1	-23 dB	F7H	EFH	
			1	1	0	0	0	−24 dB	F8H	1FH	
			1	1	0	0	1	−25 dB	F9H	9FH	
			1	1	0	1	0	-26 dB	FAH	5FH	
			1	1	0	1	1	–27 dB	FBH	DFH	
			1	1	1	0	0	-28 dB	FCH	3FH	
			1	1	1	0	1	–29 dB	FDH	BFH	
			1	1	1	1	0	-30 dB	FEH	7FH	
			1	1	1	1	1	−38.5 dB	FFH	FFH	

Note M: HEX value with MSB first L: HEX value with LSB first



4.4 TEST MODE CONTROL

The μPD9930 has the following test functions.

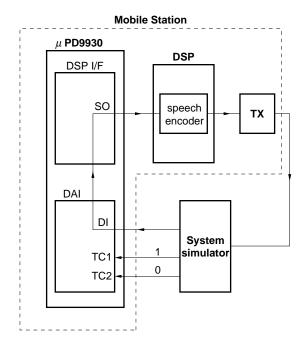
	Test function							
DAI test function	This test function is stipulated in GSM11.10. Test mode selection can be controlled by external terminal (TC1 or TC2) or internal register (ITC1, ITC2).	Test control register (TSTCR)						
Analog loopback function	Send data after BPF processing is input to LPF.							
DSP interface input/ output control function	SO, SI, SCLK and SEN terminals can be set at low level.							

An outline of test mode control is shown in Figure 4-13.

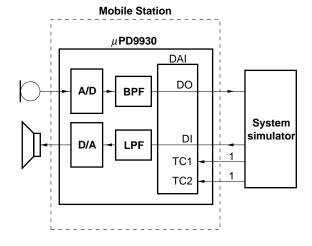


Figure 4-13 Test Mode Operation

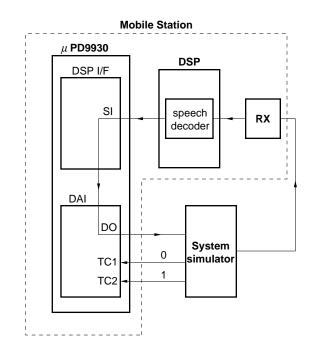
(a) DAI (speech encoder test mode)



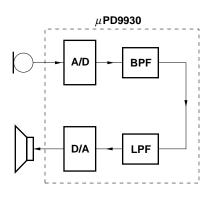
(c) DAI (A/D, D/A test mode)



(b) DAI (speech decoder test mode)



(d) Analog loopback mode





4.4.1 Test Control Register (TSTCR)

This is a 5-bit control register for selecting the test mode.

ITC1, ITC2 become valid at the rising edge of DRSTB. For the precautions when using DAI, refer to **2.1.9 DAI (Digital Audio Interface)**.

Register address **TSTCR** D1 D0 D7 D6 D5 D4 D3 D2 **TCMODE** ITC2 ITC1 LOOPBK SIOOFF 0 1 1 TCMODE DAI test mode control method selection Remarks 0 Specification of test mode by external terminals TC1 and TC2 At reset 1 Specification of test mode by test control registers ITC1 and ITC2 ITC2 ITC1 DAI test mode specification Remarks 0 0 At reset Normal operation 0 1 Speech encoder test mode 1 0 Speech decoder test mode 1 Acoustic device, A/D, D/A test mode LOOPBK Analog loopback specification Remarks At reset 0 Normal operation 1 Analog loopback SIOOFF Remarks DSP interface input/output terminal control 0 Normal operation

Figure 4-14 Test Control Register

Remark The analog loopback mode and the DAI test mode cannot be specified at the same time.

Setting of terminals SO, SI, SCLK, and SEN to low level At reset

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5. ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, DGND = AGND1 to AGND4 = 0 V)

Item	Symbol	Conditions	Ratings	Unit
Supply Voltage	V _{DD}	AVDD1, AVDD2, DVDD	-0.3 to +5.5	V
Analog Input Voltage	Vain	All analog input pins	-0.3 to V _{DD} +0.3	V
Digital Input Voltage	V _{DIN}	All digital input pins	-0.3 to V _{DD} +0.3	V
Analog Output Pin Applied Voltage	Vaout	All analog output pins	-0.3 to V _{DD} +0.3	V
Digital Output Pin Applied Voltage	VDOUT	All digital output pins	-0.3 to V _{DD} +0.3	V
Operating Ambient Temperature	TA		-30 to +85	°C
Storage Temperature	Tstg		-65 to +150	°C

- Cautions 1. Connect the AGND1 through AGND4 pins and DGND pin to an analog ground line near μPD9930 pins. Connect the DV_{DD}, AV_{DD1}, AV_{DD2} pins to an analog power supply line near μPD9930 pins.
 - 2. Do not connect output (and bidirectional) pins each other. Do not connect output (or bidirectional) pins directly to the VDD, VCC, or GND line. However, open drain pin and open collector pin can be directly connected to VDD, VCC, or GND line. If timing design is made so that no signal conflict occurs, three-state pins can also be connected directly to three-state pins of external circuit.
 - 3. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The parameters apply independently. The device should be operated within the limits specified under DC and AC Characteristics.



RECOMMENDED OPERATING RANGE ($T_A = -30 \text{ to } +85^{\circ}\text{C}$)

(1) DC Condition

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Supply Voltage	VDD	AV _{DD1} , AV _{DD2} , DV _{DD}	2.7	3.0	3.6	V
High Level Input Voltage	VIH	All digital input pins	0.7 V _{DD}		V _{DD}	V
Low Level Input Voltage	VIL	All digital input pins	0		0.3 V _{DD}	V
Analog Input Voltage	VIA	All analog input pins	0.6		1.8	V
Microphone Input						
Analog Input Voltage	Vміс	Differential: MICI+, MICI-			1.2	V_{p-p}
Gain Setting Range	Gмic	Set with external resistor	15		33	dB
Load Resistance	RLміс	Includes gain setting resistance	50			kΩ
Load Capacitance	СЬміс				20	pF
Accessory Input						
Analog Input Voltage	Vauxi	XAUXI-			1.2	V _{p-p}
Gain Setting Range	Gauxi	Set with external resistor	0		10	dB
Load Resistance	RLauxi	Includes gain setting resistance	300			kΩ
Load Capacitance	CLAUXI				20	pF
Pre-filter + Mixer Input						
Analog Input Voltage	VMIXI	MIXI			1.2	V _{p-p}
Accessory Output						
Load Resistance	RLauxo		100			kΩ
Load Capacitance	CLauxo				100	pF
Receiver 1 Output						
Load Resistance	RLREC1		100			kΩ
Load Capacitance	CLREC1				20	pF
Receiver 2 Output						
Analog Input Voltage	V _{REC2}	REC2I-			1.2	V _{p-p}
Gain Setting Range	GREC2	Set with external resistor	- ∞		+10	dB
Load Resistance	RL _{REC2}	60 nF series	2			kΩ
Load Capacitance	CLREC2	2 kΩ series			60	nF
Reference Voltage Output						
Load Capacitance	СЬАСОМ	XACOMO, RACOMO	0.2		10	μF

(2) Frame Signal (FSYNC) and Reset Signal (RESETB)

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
FSYNC Frequency	fs		7.995	8.000	8.005	kHz
FSYNC High Level Width	twns		2.0			μs
FSYNC Low Level Width	twLs		2.0			μs
FSYNC Rise Time	tr				20	ns
FSYNC Fall Time	t _f				20	ns
RESETB Low Level Width	trsl		260			ns



(3) Microcontroller Interface

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
MCLK Cycle Time	tmcy		240			ns
MCLK High Level Width	tмсн		100			ns
MCLK Low Level Width	t MCL		100			ns
MCLK Rise Time	t MR				20	ns
MCLK Fall Time	tmF				20	ns
MDAT Setup Time to MSTR ↑	tsumda		50			ns
MDAT Hold Time from MCLK ↑	thmda		50			ns
MSTR High Level Width	twmst		320			ns
MCLK Setup Time to MSTR ↑	tsumck		0			ns
MSTR Setup Time to MCLK ↑	tsимsт		100			ns

(4) DSP Interface

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
SI Setup Time to SCLK ↓	tsusi		200			ns
SI Hold Time from SCLK \downarrow	thsi		200			ns

(5) DAI

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
DI Setup Time to DCLK ↑	t sudi		200			ns
DI Hold Time from DCLK ↑	thdi		200			ns
TC1, TC2 Rise Time	t TR		50			ns
TC1, TC2 Fall Time	tтғ		50			ns
DRSTB Low Level Width	t _{DRSL}		130			μs
DRSTB Rise Time	torr				20	ns
DRSTB Fall Time	t DRF				20	ns
DAI Mode Setting Time 1	t TCF		60			ms
DAI Mode Setting Time 2	t TCR		260			μs
REQB Low Level Width	t drql		130			μs
REQB High Level Width	t DRQH		130			μs
REQB Rise Time	tdrqr				20	ns
REQB Fall Time	t _{DRQF}				20	ns



CAPACITANCE ($T_A = 25^{\circ}C$)

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Digital Output Pin Capacitance	Сор	f = 1 MHz			20	pF
Digital Input Pin Capacitance	Сід	f = 1 MHz			20	pF

DC CHARACTERISTICS ($T_A = 25^{\circ}C$, $V_{DD} = 2.7$ to 3.6 V (GND standard))

(1) Current Consumption

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current in Normal Mode	ldd1	Microphone input (1020 Hz: -10 dBm0) Accessory input: Power down serial input (1020 Hz: -10 dBm0) Accessory output: Power up Receiver 1, 2: Power up		7.0	9.0	mA
Circuit Current in DAI Operation	IDD2	Microphone input (1020 Hz: -10 dBm0) Accessory input: Power down serial input (1020 Hz: -10 dBm0) Accessory output: Power up Receiver 1, 2: Power up		7.5	10.0	mA
Circuit Current in Standby Mode	Ірр3	DI, DRSTB, TC1, TC2: Open FSYNC: 8 kHz Other digital input pins: 0 or Vbb		50	100	μΑ

(2) Digital Part

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Digital Input Leak Current	Ігн	VI = VDD			1.0	μΑ
	ILL	V ₁ = 0	-1.0			μΑ
Pull-Up/Down Current	lı∟	$V_{DD} = 3.3 \text{ V}, 0 \leq V_{I} \leq V_{DD}$			100	μΑ
Low Level Output Voltage	Vol	IoL = 2.0 mA			0.4	V
High Level Output Voltage	Vон	lон = −2.0 mA	2.4			V



(3) Analog Part

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Pre-filter + Mixer						
Volume Range	GPRF		-3		0	dB
Volume Accuracy	ΔG_PRF	Volume 0 dB standard	-3.2	-3.0	-2.8	dB
Cross-Talk 1 between Input Channels	CT _{IN1}	Microphone input amplifier: Power down MICI = 1.2 V _{P-P} XAUXI- = 0 V _{P-P} Accessory input gain setting: 0 dB			-45	dB
Cross-Talk 2 between Input Channels	CT _{IN2}	Accessory input amplifier: Power down MICI = 0 $V_{P^{-p}}$ XAUXI- = 1.2 $V_{P^{-p}}$ Accessory input gain setting: 0 dB			-45	dB
Accessory Output	'					
Maximum Output Voltage	VAMAX				1.2	V _{p-p}
Receiver 1 Output			l	I	I	
Maximum Output Voltage	V _{R1MAX}				1.2	V _{p-p}
Volume Range	GREC1		-31		0	dB
Volume Accuracy	∆Grec1	Volume: 0 to -16 dB	-1.5	-1.0	-0.5	dB
		Volume ^{Note} : -17 to -31 dB	-2.0	-1.0	0.0	dB
Receiver 2 Output	•		•		•	•
Maximum Output Voltage	V _{R2MAX}	Distortion factor 4 % (MAX.)			4	V _{p-p}
Reference Voltage Output						
Output Voltage	Vасом	XACOMO, RACOMO		1.2		V

Note Simple decrease in the gain due to drop of volume is guaranteed.

(4) Tone Generator

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output Signal Level	V _{TN1}	Tone 1	-2.93		-2.73	dBm0
	V _{TN2}	Tone 2	-5.93		-5.73	
Frequency Deviation	ΔΕτη	0.3 to 3.4 kHz	-5		+5	Hz
Distortion Factor	TNSD	Accessory output	30			dB
Tone Volume Range	GTN		-38.5		0	dB
Tone Volume Accuracy	ΔG tn	Volume: 0 to -30 dB (1 dB steps)	-1.4	-1.0	-0.8	dB

*



AC CHARACTERISTICS

(1) DSP Interface (TA = -30 to +85°C, V DD = 2.7 to 3.6 V, CL = 100 pF)

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
SCLK Cycle Time	tscy			3906		ns
SCLK High Level Width	tscн			1953		ns
SCLK Low Level Width	tscl			1953		ns
SCLK Rise Time	tsr				20	ns
SCLK Fall Time	tsf				20	ns
SCLK Delay Time from FSYNC ↑	tosclk				1.0	μs
SEN ↑ Delay Time from FSYNC ↑	tdsenr				80	ns
SEN ↓ Delay Time from SCLK ↑: Mode 1 SEN ↓ Delay Time from SCLK ↓: Mode 2	tosenf				80	ns
SO Output Delay Time from SCLK ↑: Mode 1 SO Output Delay Time from SCLK ↓: Mode 2	toso				40	ns

(2) DAI (TA = $-30 \text{ to } +85^{\circ}\text{C}$, V DD = 2.7 to 3.6 V, CL = 100 pF)

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
DCLK Cycle Time	tdcy			9615		ns
DCLK High Level Width	tосн			4808		ns
DCLK Low Level Width	tocl			4808		ns
DCLK Rise Time	t DR				20	ns
DCLK Fall Time	t DF				20	ns
DCLK Delay Time from FSYNC ↑	todclk				200	ns
DO Output Delay Time from DCLK ↓	todo				200	ns

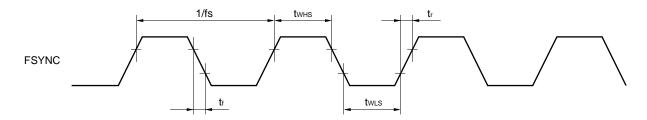
(3) Others (Digital Output) (TA = -30 to +85°C, V DD = 2.7 to 3.6 V, CL = 100 pF)

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
TIMER/RINGER Rise Time	t ddr	TIMER pin and RINGER pin			50	ns
TIMER/RINGER Fall Time	todf	TIMER pin and RINGER pin			50	ns

 \bigstar

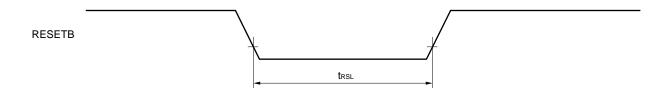


Frame signal (FSYNC)



Remark During normal operation or the power up/down sequence, be sure to input the frame signal.

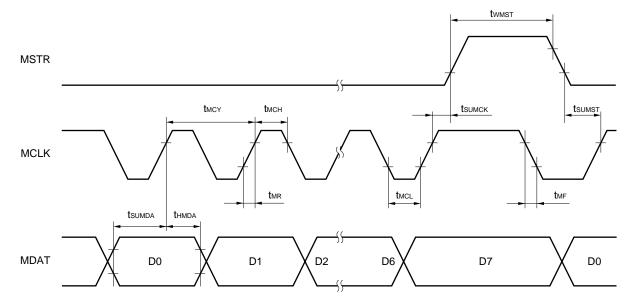
Reset signal (RESETB)



Remarks 1. The reset signal is input as it is without shaping, so take full precautions against noise.

2. A power on reset circuit is not incorporated, so be sure to set RESET to low after turning the power on.

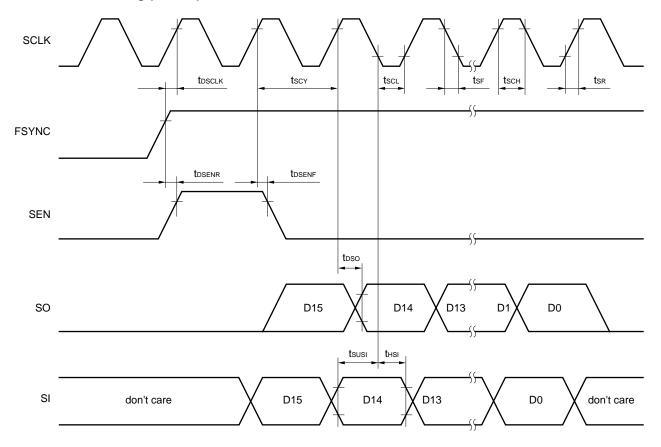
★ Microcontroller interface timing



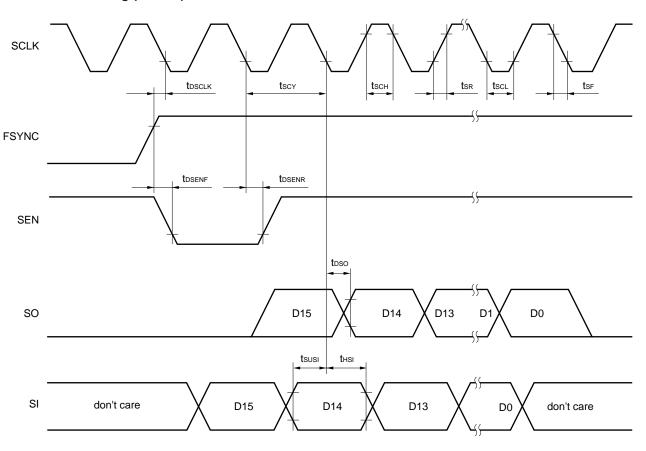
Remark D0 to D7: Microcontroller command (LSB first)



DSP interface timing (mode 1)

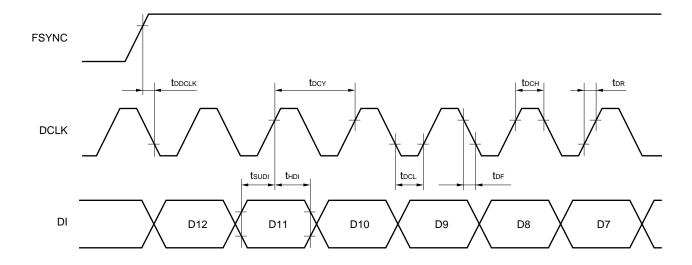


DSP interface timing (mode 2)



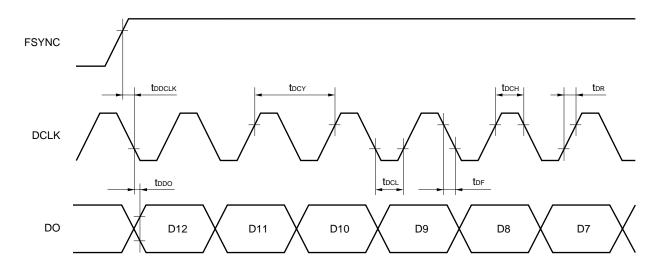


DAI input timing



Remark D12 to D0: Input data (MSB first)

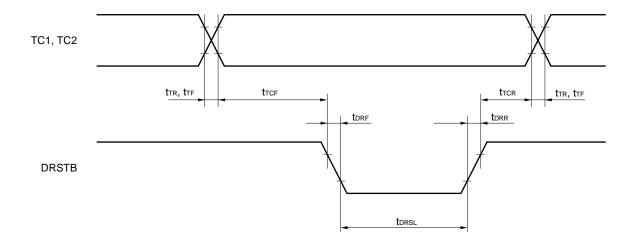
DAI output timing



Remark D12 to D0: Output data (MSB first)



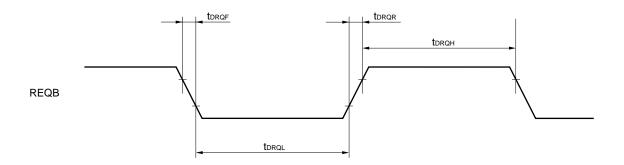
TC1, TC2, DRSTB input timing



TIMER, RINGER output timing



REQB input timing





TRANSMISSION CHARACTERISTICS

Transmission characteristics are as indicated below unless otherwise specified.

Analog input

Analog input signal (-10 dBm0, 1020 Hz) → accessory input part

Accessory input: Set gain 0 dB Microphone input: Power down Pre-filter + mixer: Set gain 0 dB

Analog output

Analog output signal \rightarrow accessory output part

Receiver output: Power down

· Digital gain set

Send and receive: 0 dB

• Digital input signal level: 0 dBm0

• $T_A = 25^{\circ}C$, V DD = 2.7 to 3.6 V (GND standard)

(1) Send/Receive Zero Transmission Level (0 dBm0 level)

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Send Zero Transmission Level	Votlpx	600 Ω standard		-8.4		dBm
Receive Zero Transmission Level	Votlpr	600 Ω standard		-8.4		dBm

(2) Gain Characteristics

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Send Gain Deviation	Gx		-0.5		+0.5	dB
Receive Gain Deviation	GR		-0.5		+0.5	dB
Send Gain Deviation Temperature Power Fluctuation	ΔGx		-0.4		+0.4	dB
Receive Gain Deviation Temperature Power Fluctuation	ΔGR		-0.4		+0.4	dB

(3) Transmission Loss Level

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Send Transmission Loss Level	Gтx	+3 to -40 dBm0	-0.4		+0.4	dB
		-40 to -50 dBm0	-0.6		+0.6	dB
		-50 to -55 dBm0	-1.2		+1.2	dB
Receive Transmission Loss	GTR	+3 to -40 dBm0	-0.4		+0.4	dB
Level		-40 to -50 dBm0	-0.6		+0.6	dB
		−50 to −55 dBm0	-1.2		+1.2	dB



(4) Transmission Gain Frequency Characteristics

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Send Transmission Gain	G _{RX1}	60 Hz			-23	dB
Frequency Characteristics	G _{RX2}	200 Hz	-2.5		0	dB
	GRX3	0.3 to 3.0 kHz	-0.3		+0.3	dB
	G _{RX4}	3.2 kHz	-0.65		+0.3	dB
	G _{RX5}	3.4 kHz	-0.8		0	dB
	G _{RX6}	4.0 kHz			-14	dB
	G _{RX7}	4.6 kHz or more			-28	dB
Receive Transmission Gain	G _{RR3}	0.3 to 3.0 kHz	-0.3		+0.3	dB
Frequency Characteristics	G _{RR4}	3.2 kHz	-0.65		+0.3	dB
	G _{RR5}	3.4 kHz	-0.8		0	dB
	G _{RR6}	4.0 kHz			-14	dB
	Grr7	4.6 kHz or more			-28	dB

(5) Noise Characteristics

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Send Noise	Nxc	Microphone power down, XAUXI- $ ightarrow$			25	dBrnc0
		ACOM, gain 0 dB, C message filter			-65	dBm0c
Receive Noise	N _{RC1}	C message filter, input +0 code from SI			25	dBrnc0
					-65	dBm0c
Single Frequency Noise	Nsf	Send input → Receive output			-50	dBm0
Cross-Talk between Send and Receive Channels	CTTR	No sidetone pass, microphone power down input 0 dBm0 and 1020 Hz from XAUXI—input +0 code from SI			-60	dB
Cross-Talk between Receive and Send Channels	СТят	No sidetone pass, microphone power down XAUXI- \rightarrow ACOM input 0 dBm0 and 1020 Hz from SI			-60	dB
Power Supply Voltage Variation Rejection	PSRR	$V_{DD} \pm 100 \text{ mV}_{0-p}$ signal application $f = 0 \text{ to } 3.4 \text{ kHz}$	30			dB

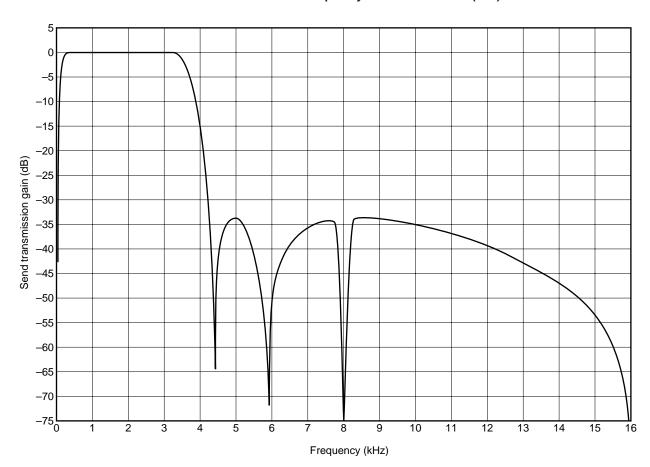


(6) Distortion Factor Characteristics

*

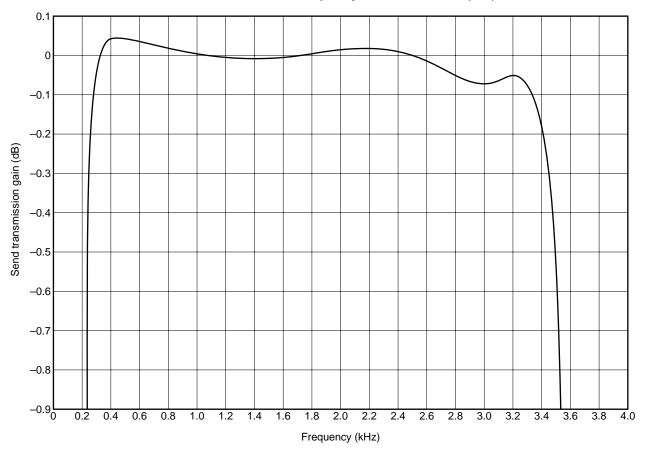
Item	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Send Channel Total Power Distortion Factor	SDx	0 to -10 dBm0		35			dB
		-40 dBm0		25			
		-45 dBm0		20			
Receive Channel Total	nel Total SDR 0 to -10 dBm0		35			dB	
Power Distortion Factor		-40 dBm0		25			
		-45 dBm0		20			
Absolute Delay	DA	XAUXI− → RAUXO				550	μs
Delay Distortion Frequency Characteristics	Do	XAUXI- → RAUXO	500 Hz			1.40	ms
			600 Hz			0.70	
			1 kHz			0.20	
			2.6 kHz			0.20	
			2.8 kHz			1.40	

Send Transmission Gain Frequency Characteristics 1 (GRX)

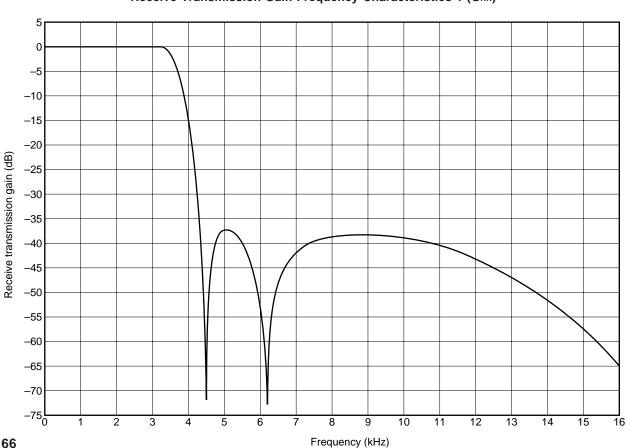




Send Transmission Gain Frequency Characteristics 2 (GRX)

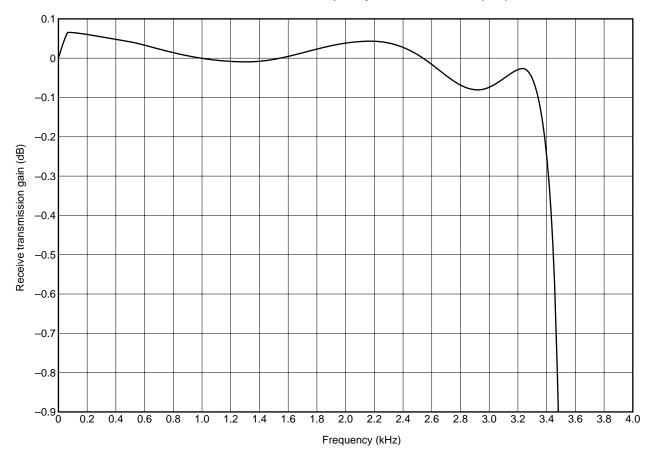


Receive Transmission Gain Frequency Characteristics 1 (GRR)



NEC

Receive Transmission Gain Frequency Characteristics 2 (GRR)





★ Send/receive zero transmission level (0 dBm0 level) is explained below for your reference.

(a) Send zero transmission level

Analog output signal level at which the digital input signal level of the D/A converter becomes 0 dBm0.

(b) Receive zero transmission level

Analog input signal level at which the digital output signal level of the A/D converter becomes 0 dBm0.

(c) Analog signal level (dBm)

The conversion expression of the amplitude voltage of a signal and an analog signal level is as follows:

X = 10 logW

X: analog signal level (dBm)

W: analog signal power (mW)

 $W = (V^2/R) \times 10^3$

V: effective value of analog signal (AC) (Vrms)

R: resistance (Ω)

With the μ PD9930, the signal voltage (effective value) can be calculated if R = 600 Ω and X = -8.4 dBm are substituted.

W = 0.1445 (mW)

V = 0.294 (Vrms)

To calculate V_{0-p} , multiply the signal voltage (effective value) by $\sqrt{2}$.

 $V_{0-p} = 0.416 (V)$

(d) Digital signal level (dBm0)

Signal level where the level of the full swing of the digital output value of the A/D converter and the digital input value of the D/A converter is considered to be 3.17 dBm0 (the amplitude of the analog signal is 1.2 V_{p-p} where the gain of the microphone input or accessory input is 0 dB).

<Level diagram>

This diagram indicates the range in which adjustments can be made by using each amplifier and gain control function.

Example: Input level at which digital output of linear codec is -10 dBm0 is -33 dBm.

(Conditions)

Microphone amplifier gain during microphone input: 15 dB

Analog gain control: 0 dB Digital gain control: 0 dB

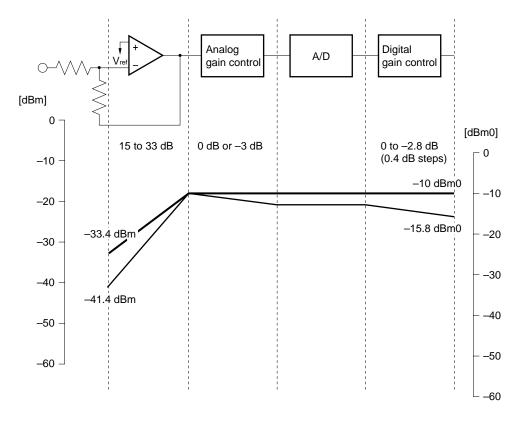
Output level at which digital input of linear codec is -10 dBm0 is -18.4 dBm.

(Conditions)

During receiver output Analog gain control: 0 dB Digital gain control: 0 dB



★ Voice send level diagram (microphone input)



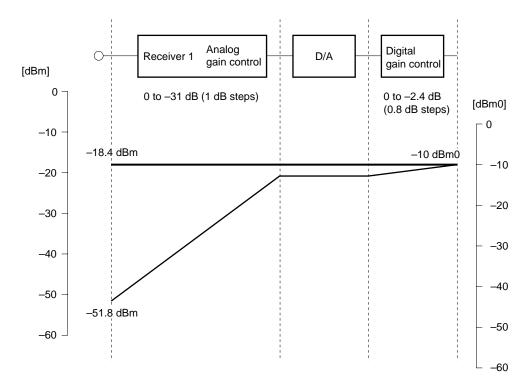
Remarks 1. Thick line: Indicates case where gain of microphone amplifier is set to 15 dB, gain of analog gain control to 0 dB, and gain of digital gain control to 0 dB.

Thin line: Indicates case where gain of microphone amplifier is set to 33 dB, gain of analog gain control to -3 dB, and gain of digital gain control to -2.8 dB.

2. Overload level: 3.17 dBm0.



★ Voice receive level diagram (receiver output)



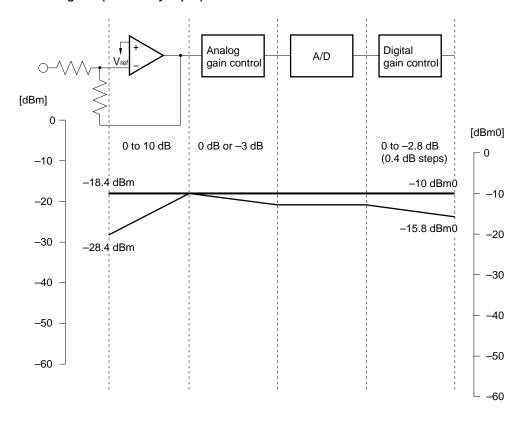
Remarks 1. Thick line: Indicates case where gain of analog gain control is set to 0 dB and gain of digital gain control to 0 dB.

Thin line: Indicates case where gain of analog gain control is set to -31 dB and gain of digital gain control to -2.4 dB.

2. Overload level: 3.17 dBm0.



★ Voice send level diagram (accessory input)



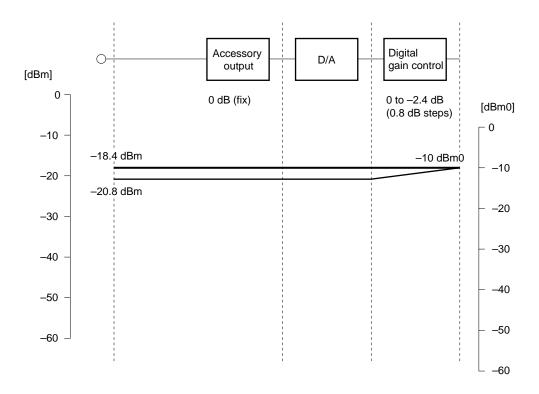
Remarks 1. Thick line: Indicates case where gain of microphone amplifier is set to 0 dB, gain of analog gain control to 0 dB, and gain of digital gain control to 0 dB.

Thin line: Indicates case where gain of microphone amplifier is set to 10 dB, gain of analog gain control to -3 dB, and gain of digital gain control to -2.8 dB.

2. Overload level: 3.17 dBm0.



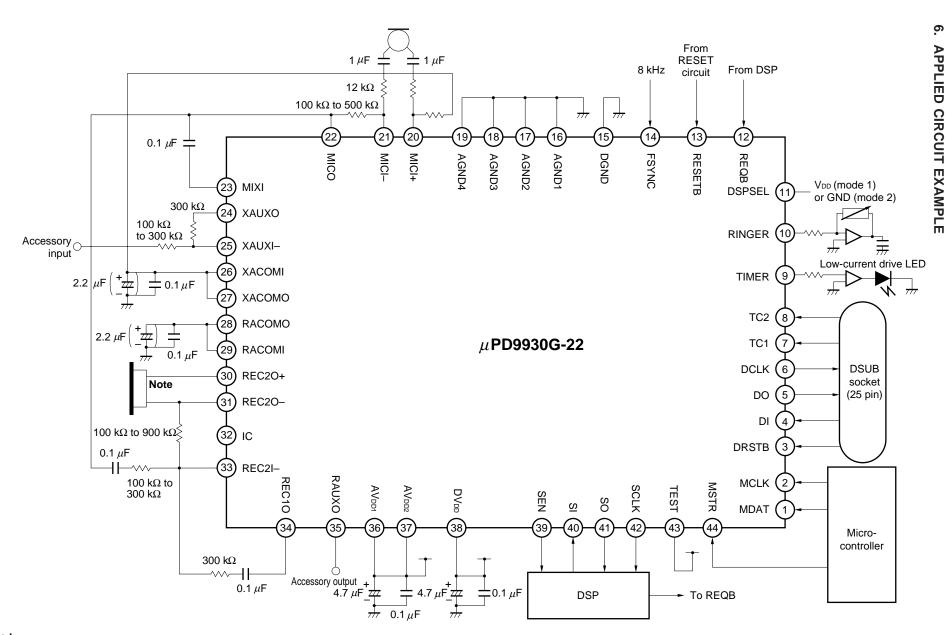
★ Voice receive level diagram (accessory output)



Remarks 1. Thick line: Indicates case where gain of digital gain control is set to 0 dB.

Thin line: Indicates case where gain of digital gain control is set to -2.4 dB.

2. Overload level: 3.17 dBm0.

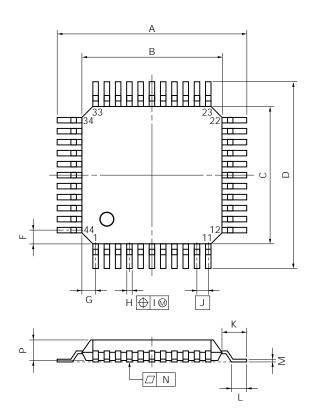


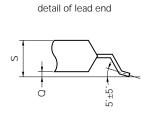
Note When connecting a dynamic receiver, use a drive amplifier.



7. PACKAGE DRAWINGS

44 PIN PLASTIC QFP (□10)





P44G-80-22-2

NOTE

Each lead centerline is located within 0.15 mm (0.006 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
Α	13.6±0.4	0.535+0.017
В	10.0±0.2	0.394+0.008
С	10.0±0.2	0.394+0.008
D	13.6±0.4	0.535+0.017
F	1.0	0.039
G	1.0	0.039
Н	0.35±0.10	0.014+0.004
I	0.15	0.006
J	0.8 (T.P.)	0.031 (T.P.)
K	1.8±0.2	0.071+0.008
L	1.0±0.2	0.039+0.009
М	0.15 ^{+0.10} _{-0.05}	0.006+0.004
N	0.15	0.006
Р	1.45±0.1	0.057 ^{+0.005} _{-0.004}
Q	0.05±0.05	0.002±0.002
S	1.65 MAX.	0.065 MAX.



★ 8. RECOMMENDED SOLDERING CONDITIONS

The following conditions must be met for soldering conditions of the μ PD9930.

For more details, refer to our document "Semiconductor Device Mounting Technology Manual" (C10535E).

Please consult with our sales offices in case other soldering process is used, or in case the soldering is done under different conditions.

Type of Surface Mount Device

 μ PD9930G-22: 44-pin plastic QFP (10 x 10 mm)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak temperature of package surface: 235°C or below, Reflow time: 30 seconds or below (210°C or higher), Number of reflow processes: MAX. 2 Exposure limitNote: 7 days (10 hours pre-baking is required at 125°C afterwards)	IR35-107-2
VPS	Peak temperature of package surface: 215°C or below, Reflow time: 40 seconds or below (200°C or higher), Number of reflow processes: MAX. 2 Exposure limitNote: 7 days (10 hours pre-baking is required at 125°C afterwards)	VP15-107-2
Wave soldering	Soldering bath temperature: 260°C or below, Reflow time: 10 seconds or below, Number of reflow processes: 1 Preheating temperature: 120°C MAX. (package surface temperature) Exposure limitNote: 7 days (10 hours pre-baking is required at 125°C afterwards)	WS60-107-1
Partial heating method	Terminal temperature: 300°C or below, Time: 3 seconds or below (Per one side of the device).	_

Note Exposure limit before soldering after dry-pack package is opened.

Storage conditions: 25°C and relative humidity at 65 % or less.

Caution Do not apply more than one soldering method at any one time, except for "Partial heating method".

[MEMO]



NOTES FOR CMOS DEVICES -

1) PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note: Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

(2) HANDLING OF UNUSED INPUT PINS FOR CMOS

Note: No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS device behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

(3) STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note: Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

[MEMO]

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The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

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While NEC Corporation has been making continuous effort to enhance the reliability of its semiconductor devices, the possibility of defects cannot be eliminated entirely. To minimize risks of damage or injury to persons or property arising from a defect in an NEC semiconductor device, customers must incorporate sufficient safety measures in its design, such as redundancy, fire-containment, and anti-failure features.

NEC devices are classified into the following three quality grades:

"Standard", "Special", and "Specific". The Specific quality grade applies only to devices developed based on a customer designated "quality assurance program" for a specific application. The recommended applications of a device depend on its quality grade, as indicated below. Customers must check the quality grade of each device before using it in a particular application.

Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots

Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

The quality grade of NEC devices is "Standard" unless otherwise specified in NEC's Data Sheets or Data Books. If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.

Anti-radioactive design is not implemented in this product.

M4 96.5